

Preliminary Technical Data
FEATURES

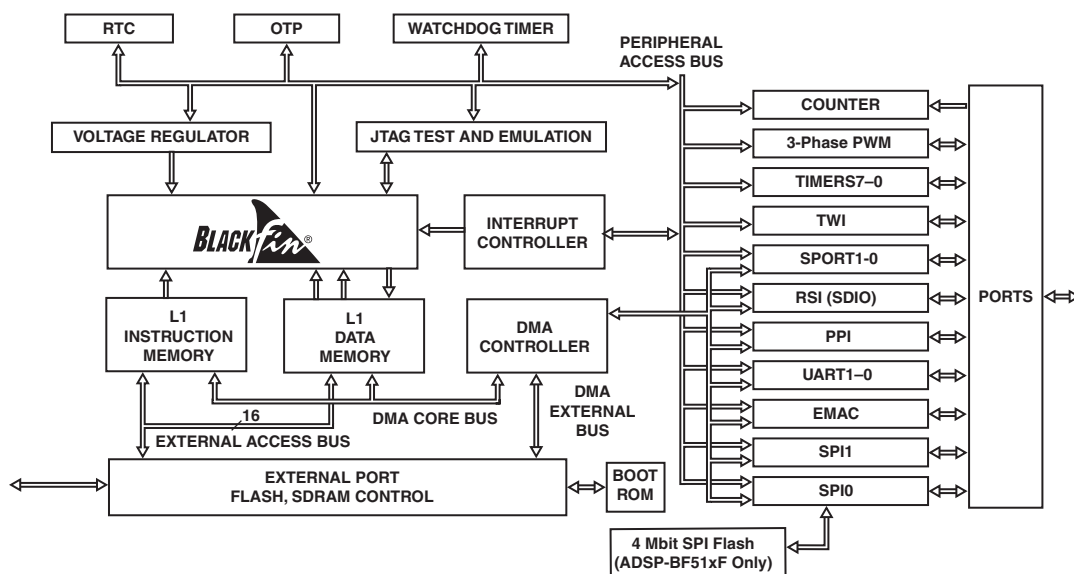
Up to 400 MHz high-performance Blackfin processor
 Two 16-bit MACs, two 40-bit ALUs, four 8-bit video ALUs,
 40-bit shifter
 RISC-like register and instruction model for ease of
 programming and compiler-friendly support
 Advanced debug, trace, and performance monitoring
 1.1 V to 1.4 V core V_{DD} with on-chip voltage regulation
 1.8 V, 2.5 V, or 3.3 V I/O
 Up to 3.3 V tolerant I/O with 5 V tolerant signals for TWI
 tbd-ball CSP_BGA (12 mm x 12 mm)
 176-lead LQFP

MEMORY

116K bytes of on-chip memory
 External memory controller with glueless support for SDRAM
 and asynchronous 8-bit and 16-bit memories
 Optional 4 Mbit on-chip SPI flash with boot option
 Flexible booting options from internal SPI flash, OTP mem-
 ory, external SPI and parallel memory, or from SPI and
 UART host devices
 Code security with Lockbox™ secure technology
 One-time-programmable (OTP) memory
 Memory management unit providing memory protection

PERIPHERALS

IEEE 802.3-compliant 10/100 ethernet MAC
 with IEEE-1588 support
 Parallel peripheral interface (PPI), supporting ITU-R 656
 video data formats
 Two dual-channel, full-duplex synchronous serial ports
 (SPORTs), supporting eight stereo I²S channels
 12 peripheral DMAs, two mastered by the ethernet MAC
 Two memory-to-memory DMAs with external request lines
 Event handler with 53 interrupt inputs
 Two serial peripheral interfaces (SPI)
 Removable storage interface (RSI) controller for MMC, SD,
 and CE-ATA
 Two UARTs with IrDA® support
 Two-wire interface (TWI) controller
 Eight 32-bit timers/counters with PWM support
 Three-phase 16-bit center-based PWM unit
 32-bit rotary counter
 Real-time clock (RTC) and watchdog timer
 32-bit core timer
 40 general-purpose I/Os (GPIOs), with programmable drivers
 and hysteresis
 Debug/JTAG interface
 On-chip PLL capable of 0.5× to 64× frequency multiplication



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Rev. PrA

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REVISION HISTORY

2/08—Revision PrA: Initial Version

From ADSP-BF52x PrD

GENERAL DESCRIPTION

The ADSP-BF512/514/516 processor is a member of the Blackfin family of products, incorporating the Analog Devices/Intel Micro Signal Architecture (MSA). Blackfin processors combine a dual-MAC state-of-the-art signal processing engine, the advantages of a clean, orthogonal RISC-like microprocessor instruction set, and single-instruction, multiple-data (SIMD) multimedia capabilities into a single instruction-set architecture.

The ADSP-BF512/514/516 processor is completely code compatible with other Blackfin processors.

Table 1. Processor Comparison

Feature	ADSP-BF512	ADSP-BF512F	ADSP-BF514	ADSP-BF514F	ADSP-BF516	ADSP-BF516F
Ethernet MAC	–	–	–	–	1	1
RSI	–	–	1	1	1	1
TWI	1	1	1	1	1	1
SPORTs	2	2	2	2	2	2
UARTs	2	2	2	2	2	2
SPIs	2	2	2	2	2	2
GP Timers	8	8	8	8	8	8
Watchdog Timers	1	1	1	1	1	1
RTC	1	1	1	1	1	1
PPI	1	1	1	1	1	1
Internal 4 Mbit SPI flash	–	1	–	1	–	1
Rotary Counter	1	1	1	1	1	1
3-phase PWM Pairs	3	3	3	3	3	3
GPIOs	40	40	40	40	40	40
Memory (bytes)	L1 Instruction SRAM	32K				
	L1 Instruction SRAM/Cache	16K				
	L1 Data SRAM	32K				
	L1 Data SRAM/Cache	32K				
	L1 Scratchpad	4K				
	L3 Boot ROM	32K				
Maximum Speed Grade	400 MHz					
Package Options	176-Lead LQFP tbd-Ball CSP_BGA					

By integrating a rich set of industry-leading system peripherals and memory, Blackfin processors are the platform of choice for next-generation applications that require RISC-like programmability, multimedia support, and leading-edge signal processing in one integrated package.

PORTABLE LOW-POWER ARCHITECTURE

Blackfin processors provide world-class power management and performance. They are produced with a low power and low voltage design methodology and feature on-chip dynamic

power management, which is the ability to vary both the voltage and frequency of operation to significantly lower overall power consumption. This capability can result in a substantial reduction in power consumption, compared with just varying the frequency of operation. This allows longer battery life for portable appliances.

SYSTEM INTEGRATION

The ADSP-BF512/514/516 processor is a highly integrated system-on-a-chip solution for the next generation of embedded network connected applications. By combining industry-standard interfaces with a high performance signal processing core, cost-effective applications can be developed quickly, without the need for costly external components. The system peripherals include an IEEE-compliant 802.3 10/100 ethernet MAC with IEEE-1588 support, an RSI controller, a TWI controller, two UART ports, two SPI ports, two serial ports (SPORTs), nine general purpose 32-bit timers (eight with PWM capability), three-phase PWM for motor control, a real-time clock, a watchdog timer, and a parallel peripheral interface (PPI).

PROCESSOR PERIPHERALS

The ADSP-BF512/514/516 processor contains a rich set of peripherals connected to the core via several high bandwidth buses, providing flexibility in system configuration as well as excellent overall system performance (see the block diagram on Page 1). The ADSP-BF512/514/516 processor contains dedicated network communication modules and high speed serial and parallel ports, an interrupt controller for flexible management of interrupts from the on-chip peripherals or external sources, and power management control functions to tailor the performance and power characteristics of the processor and system to many application scenarios.

All of the peripherals, except for the general-purpose I/O, rotary counter, TWI, three-phase PWM, real-time clock, and timers, are supported by a flexible DMA structure. There are also separate memory DMA channels dedicated to data transfers between the processor's various memory spaces, including external SDRAM and asynchronous memory. Multiple on-chip buses provide enough bandwidth to keep the processor core running along with activity on all of the on-chip and external peripherals.

The ADSP-BF512/514/516 processor includes an on-chip voltage regulator in support of the processor's dynamic power management capability. The voltage regulator provides a range of core voltage levels when supplied from a single 2.25 V to 3.6 V input. The voltage regulator can be bypassed at the user's discretion.

BLACKFIN PROCESSOR CORE

As shown in [Figure 1 on Page 4](#), the Blackfin processor core contains two 16-bit multipliers, two 40-bit accumulators, two 40-bit ALUs, four video ALUs, and a 40-bit shifter. The computation units process 8-, 16-, or 32-bit data from the register file.

The compute register file contains eight 32-bit registers. When performing compute operations on 16-bit operand data, the register file operates as 16 independent 16-bit registers. All operands for compute operations come from the multiported register file and instruction constant fields.

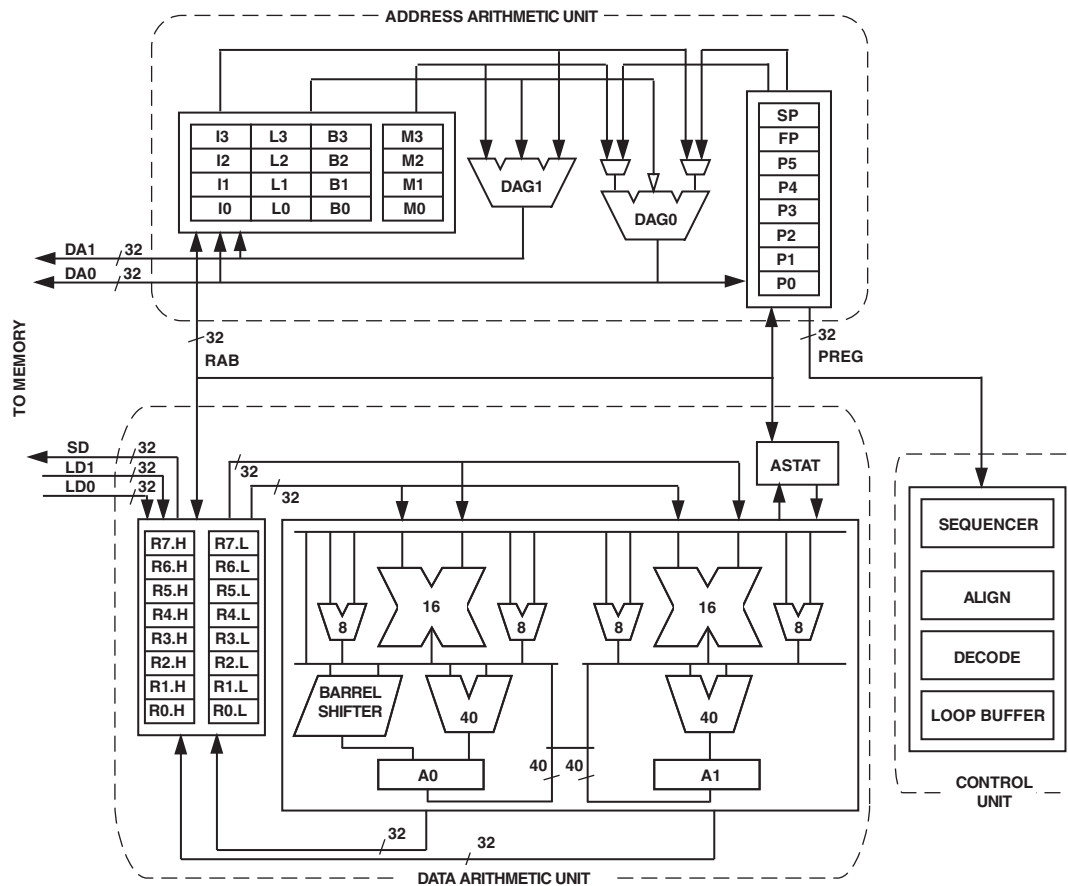


Figure 1. Blackfin Processor Core

Each MAC can perform a 16-bit by 16-bit multiply in each cycle, accumulating the results into the 40-bit accumulators. Signed and unsigned formats, rounding, and saturation are supported.

The ALUs perform a traditional set of arithmetic and logical operations on 16-bit or 32-bit data. In addition, many special instructions are included to accelerate various signal processing tasks. These include bit operations such as field extract and population count, modulo 2^{32} multiply, divide primitives, saturation and rounding, and sign/exponent detection. The set of video instructions include byte alignment and packing operations, 16-bit and 8-bit adds with clipping, 8-bit average operations, and 8-bit subtract/absolute value/accumulate (SAA) operations. Also provided are the compare/select and vector search instructions.

For certain instructions, two 16-bit ALU operations can be performed simultaneously on register pairs (a 16-bit high half and 16-bit low half of a compute register). If the second ALU is used, quad 16-bit operations are possible.

The 40-bit shifter can perform shifts and rotates and is used to support normalization, field extract, and field deposit instructions.

The program sequencer controls the flow of instruction execution, including instruction alignment and decoding. For program flow control, the sequencer supports PC relative and indirect conditional jumps (with static branch prediction), and subroutine calls. Hardware is provided to support zero-overhead looping. The architecture is fully interlocked, meaning that the programmer need not manage the pipeline when executing instructions with data dependencies.

The address arithmetic unit provides two addresses for simultaneous dual fetches from memory. It contains a multiported register file consisting of four sets of 32-bit index, modify, length, and base registers (for circular buffering), and eight additional 32-bit pointer registers (for C-style indexed stack manipulation).

Blackfin processors support a modified Harvard architecture in combination with a hierarchical memory structure. Level 1 (L1) memories are those that typically operate at the full processor speed with little or no latency. At the L1 level, the instruction memory holds instructions only. The two data memories hold data, and a dedicated scratchpad data memory stores stack and local variable information.

In addition, multiple L1 memory blocks are provided, offering a configurable mix of SRAM and cache. The memory management unit (MMU) provides memory protection for individual tasks that may be operating on the core and can protect system registers from unintended access.

The architecture provides three modes of operation: user mode, supervisor mode, and emulation mode. User mode has restricted access to certain system resources, thus providing a protected software environment, while supervisor mode has unrestricted access to the system and core resources.

The Blackfin processor instruction set has been optimized so that 16-bit opcodes represent the most frequently used instructions, resulting in excellent compiled code density. Complex DSP instructions are encoded into 32-bit opcodes, representing fully featured multifunction instructions. Blackfin processors support a limited multi-issue capability, where a 32-bit instruction can be issued in parallel with two 16-bit instructions, allowing the programmer to use many of the core resources in a single instruction cycle.

The Blackfin processor assembly language uses an algebraic syntax for ease of coding and readability. The architecture has been optimized for use in conjunction with the C/C++ compiler, resulting in fast and efficient software implementations.

MEMORY ARCHITECTURE

The ADSP-BF512/514/516 processor views memory as a single unified 4G byte address space, using 32-bit addresses. All resources, including internal memory, external memory, and I/O control registers, occupy separate sections of this common address space. The memory portions of this address space are arranged in a hierarchical structure to provide a good cost/performance balance of some very fast, low-latency on-chip memory as cache or SRAM, and larger, lower-cost and performance off-chip memory systems. See Figure 2.

The on-chip L1 memory system is the highest-performance memory available to the Blackfin processor. The off-chip memory system, accessed through the external bus interface unit (EBIU), provides expansion with SDRAM, flash memory, and SRAM, optionally accessing up to 132M bytes of physical memory.

The memory DMA controller provides high-bandwidth data-movement capability. It can perform block transfers of code or data between the internal memory and the external memory spaces.

Internal (On-Chip) Memory

The ADSP-BF512/514/516 processor has three blocks of on-chip memory providing high-bandwidth access to the core.

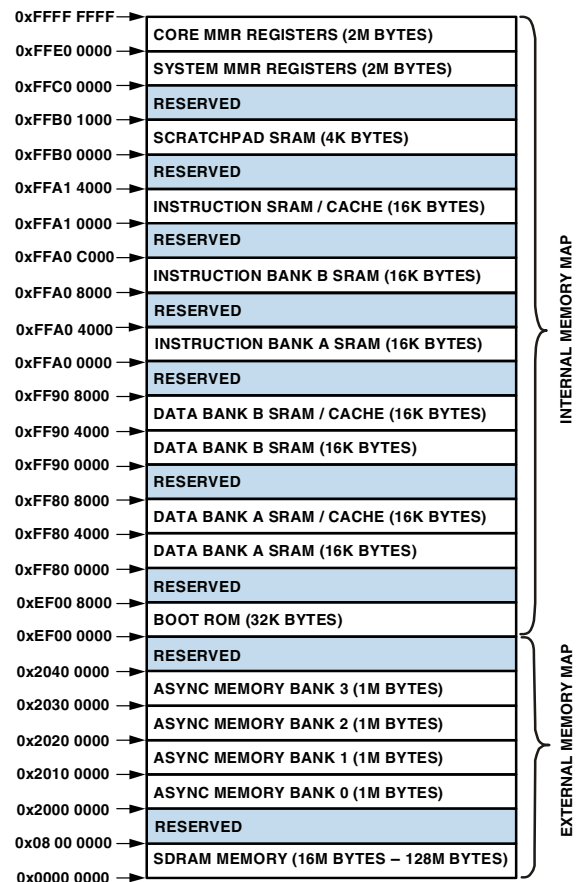


Figure 2. ADSP-BF512/514/516 Internal/External Memory Map

The first block is the L1 instruction memory, consisting of 48K bytes SRAM, of which 16K bytes can be configured as a four-way set-associative cache. This memory is accessed at full processor speed.

The second on-chip memory block is the L1 data memory, consisting of up to two banks of up to 32K bytes each. Each memory bank is configurable, offering both cache and SRAM functionality. This memory block is accessed at full processor speed.

The third memory block is a 4K byte scratchpad SRAM which runs at the same speed as the L1 memories, but is only accessible as data SRAM and cannot be configured as cache memory.

External (Off-Chip) Memory

External memory is accessed via the EBIU. This 16-bit interface provides a glueless connection to a bank of synchronous DRAM (SDRAM) as well as up to four banks of asynchronous memory devices including flash, EPROM, ROM, SRAM, and memory mapped I/O devices.

The SDRAM controller can be programmed to interface to up to 128M bytes of SDRAM. A separate row can be open for each SDRAM internal bank and the SDRAM controller supports up to four internal SDRAM banks, improving overall performance.

The asynchronous memory controller can be programmed to control up to four banks of devices with very flexible timing parameters for a wide variety of devices. Each bank occupies a 1M byte segment regardless of the size of the devices used, so that these banks are only contiguous if each is fully populated with 1M byte of memory.

Flash Memory

The ADSP-BF512F/ADSP-BF514F/ADSP-BF516F processor contains a SPI flash memory within the package of the processor and connected to SPI0. The following features are included.

- Up to tbd MHz operation
- Low power consumption
- Endurance: 100,000 cycles (typical)
- Over 100 years data retention

The ADSP-BF512F/ADSP-BF514F/ADSP-BF516F processor internally connects to the flash memory die with the MOSI, MISO, SPISSEL, and SPI_CLK signals similar to an external SPI flash. To further provide a secure processing environment, these internally connected signals are not exposed outside of the package. For this reason, programming the ADSP-BF51xF flash memory is performed by running code on the processor. It cannot be programmed from external signals nor can data transfer between the SPI flash and the processor be probed externally.

One-Time Programmable Memory

The ADSP-BF512/514/516 has 64K bits of one-time programmable non-volatile memory that can be programmed by the developer only one time. It includes the array and logic to support read access and programming. Additionally, its pages can be write protected.

OTP enables developers to store both public and private data on-chip. In addition to storing public and private key data for applications requiring security, it also allows developers to store completely user-definable data such as customer ID, product ID, and MAC address. Hence generic parts can be shipped which are then programmed and protected by the developer within this non-volatile memory.

I/O Memory Space

The ADSP-BF512/514/516 processor does not define a separate I/O space. All resources are mapped through the flat 32-bit address space. On-chip I/O devices have their control registers mapped into memory-mapped registers (MMRs) at addresses near the top of the 4G byte address space. These are separated into two smaller blocks, one which contains the control MMRs for all core functions, and the other which contains the registers needed for setup and control of the on-chip peripherals outside of the core. The MMRs are accessible only in supervisor mode and appear as reserved space to on-chip peripherals.

Booting

The ADSP-BF512/514/516 processor contains a small on-chip boot kernel, which configures the appropriate peripheral for booting. If the ADSP-BF512/514/516 processor is configured to

boot from boot ROM memory space, the processor starts executing from the on-chip boot ROM. For more information, see [Booting Modes on Page 18](#).

Event Handling

The event controller on the ADSP-BF512/514/516 processor handles all asynchronous and synchronous events to the processor. The ADSP-BF512/514/516 processor provides event handling that supports both nesting and prioritization. Nesting allows multiple event service routines to be active simultaneously. Prioritization ensures that servicing of a higher-priority event takes precedence over servicing of a lower-priority event. The controller provides support for five different types of events:

- Emulation – An emulation event causes the processor to enter emulation mode, allowing command and control of the processor through the JTAG interface.
- Reset – This event resets the processor.
- Nonmaskable Interrupt (NMI) – The NMI event can be generated by the software watchdog timer or by the NMI input signal to the processor. The NMI event is frequently used as a power-down indicator to initiate an orderly shut-down of the system.
- Exceptions – Events that occur synchronously to program flow; that is, the exception is taken before the instruction is allowed to complete. Conditions such as data alignment violations and undefined instructions cause exceptions.
- Interrupts – Events that occur asynchronously to program flow. They are caused by input signals, timers, and other peripherals, as well as by an explicit software instruction.

Each event type has an associated register to hold the return address and an associated return-from-event instruction. When an event is triggered, the state of the processor is saved on the supervisor stack.

The ADSP-BF512/514/516 processor event controller consists of two stages, the core event controller (CEC) and the system interrupt controller (SIC). The core event controller works with the system interrupt controller to prioritize and control all system events. Conceptually, interrupts from the peripherals enter into the SIC, and are then routed directly into the general-purpose interrupts of the CEC.

Core Event Controller (CEC)

The CEC supports nine general-purpose interrupts (IVG15–7), in addition to the dedicated interrupt and exception events. Of these general-purpose interrupts, the two lowest-priority interrupts (IVG15–14) are recommended to be reserved for software interrupt handlers, leaving seven prioritized interrupt inputs to support the peripherals of the ADSP-BF512/514/516

processor. Table 2 describes the inputs to the CEC, identifies their names in the event vector table (EVT), and lists their priorities.

Table 2. Core Event Controller (CEC)

Priority (0 is Highest)	Event Class	EVT Entry
0	Emulation/Test Control	EMU
1	Reset	RST
2	Nonmaskable Interrupt	NMI
3	Exception	EVX
4	Reserved	—
5	Hardware Error	IVHW
6	Core Timer	IVTMR
7	General-Purpose Interrupt 7	IVG7
8	General-Purpose Interrupt 8	IVG8
9	General-Purpose Interrupt 9	IVG9
10	General-Purpose Interrupt 10	IVG10
11	General-Purpose Interrupt 11	IVG11
12	General-Purpose Interrupt 12	IVG12
13	General-Purpose Interrupt 13	IVG13
14	General-Purpose Interrupt 14	IVG14
15	General-Purpose Interrupt 15	IVG15

System Interrupt Controller (SIC)

The system interrupt controller provides the mapping and routing of events from the many peripheral interrupt sources to the prioritized general-purpose interrupt inputs of the CEC. Although the ADSP-BF512/514/516 processor provides a default mapping, the user can alter the mappings and priorities of interrupt events by writing the appropriate values into the interrupt assignment registers (SIC_IARx). Table 3 describes the inputs into the SIC and the default mappings into the CEC.

Table 3. Peripheral Interrupt Assignment

Peripheral Interrupt Event	General Purpose Interrupt (at Reset)	Peripheral Interrupt ID	Default Core Interrupt ID	SIC Registers	
PLL Wakeup Interrupt	IVG7	0	0	IAR0	IMASK0 and ISR0
DMA Error 0 (generic)	IVG7	1	0	IAR0	IMASK0 and ISR0
DMAR0 Block Interrupt	IVG7	2	0	IAR0	IMASK0 and ISR0
DMAR1 Block Interrupt	IVG7	3	0	IAR0	IMASK0 and ISR0
DMAR0 Overflow Error	IVG7	4	0	IAR0	IMASK0 and ISR0
DMAR1 Overflow Error	IVG7	5	0	IAR0	IMASK0 and ISR0
PPI Error	IVG7	6	0	IAR0	IMASK0 and ISR0
MAC Status	IVG7	7	0	IAR0	IMASK0 and ISR0
SPORT0 Status	IVG7	8	0	IAR1	IMASK0 and ISR0
SPORT1 Status	IVG7	9	0	IAR1	IMASK0 and ISR0
PTP Error Interrupt	IVG7	10	0	IAR1	IMASK0 and ISR0
Reserved	IVG7	11	0	IAR1	IMASK0 and ISR0
UART0 Status	IVG7	12	0	IAR1	IMASK0 and ISR0
UART1 Status	IVG7	13	0	IAR1	IMASK0 and ISR0
RTC	IVG8	14	1	IAR1	IMASK0 and ISR0
DMA 0 Channel (PPI)	IVG8	15	1	IAR1	IMASK0 and ISR0
DMA 3 Channel (SPORT0 RX)	IVG9	16	2	IAR2	IMASK0 and ISR0
DMA 4 Channel (SPORT0 TX/RSI)	IVG9	17	2	IAR2	IMASK0 and ISR0
DMA 5 Channel (SPORT1 RX/SPI1)	IVG9	18	2	IAR2	IMASK0 and ISR0

Table 3. Peripheral Interrupt Assignment

Peripheral Interrupt Event	General Purpose Interrupt (at Reset)	Peripheral Interrupt ID	Default Core Interrupt ID	SIC Registers	
DMA 6 Channel (SPORT1 TX)	IVG9	19	2	IAR2	IMASK0 and ISR0
TWI	IVG10	20	3	IAR2	IMASK0 and ISR0
DMA 7 Channel (SPI0)	IVG10	21	3	IAR2	IMASK0 and ISR0
DMA8 Channel (UART0 RX)	IVG10	22	3	IAR2	IMASK0 and ISR0
DMA9 Channel (UART0 TX)	IVG10	23	3	IAR2	IMASK0 and ISR0
DMA10 Channel (UART1 Rx)	IVG10	24	3	IAR3	IMASK0 and ISR0
DMA11 Channel (UART1 Tx)	IVG10	25	3	IAR3	IMASK0 and ISR0
OTP Memory Interrupt	IVG11	26	4	IAR3	IMASK0 and ISR0
GP Counter	IVG11	27	4	IAR3	IMASK0 and ISR0
DMA1 Channel (MAC RX)	IVG11	28	4	IAR3	IMASK0 and ISR0
Port H Interrupt A	IVG11	29	4	IAR3	IMASK0 and ISR0
DMA2 Channel (MAC TX)	IVG11	30	4	IAR3	IMASK0 and ISR0
Port H Interrupt B	IVG11	31	4	IAR3	IMASK0 and ISR0
Timer 0	IVG12	32	5	IAR4	IMASK1 and ISR1
Timer 1	IVG12	33	5	IAR4	IMASK1 and ISR1
Timer 2	IVG12	34	5	IAR4	IMASK1 and ISR1
Timer 3	IVG12	35	5	IAR4	IMASK1 and ISR1
Timer 4	IVG12	36	5	IAR4	IMASK1 and ISR1
Timer 5	IVG12	37	5	IAR4	IMASK1 and ISR1
Timer 6	IVG12	38	5	IAR4	IMASK1 and ISR1
Timer 7	IVG12	39	5	IAR4	IMASK1 and ISR1
Port G Interrupt A	IVG12	40	5	IAR5	IMASK1 and ISR1
Port G Interrupt B	IVG12	41	5	IAR5	IMASK1 and ISR1
MDMA Stream 0	IVG13	42	6	IAR5	IMASK1 and ISR1
MDMA Stream 1	IVG13	43	6	IAR5	IMASK1 and ISR1
Software Watchdog Timer	IVG13	44	6	IAR5	IMASK1 and ISR1
Port F Interrupt A	IVG13	45	6	IAR5	IMASK1 and ISR1
Port F Interrupt B	IVG13	46	6	IAR5	IMASK1 and ISR1
SPI0 Status	IVG7	47	0	IAR5	IMASK1 and ISR1
SPI1 Status	IVG7	48	0	IAR6	IMASK1 and ISR1
Reserved	IVG7	49	0	IAR6	IMASK1 and ISR1
Reserved	IVG7	50	0	IAR6	IMASK1 and ISR1
RSI Interrupt0	IVG10	51	3	IAR6	IMASK1 and ISR1
RSI Interrupt1	IVG10	52	3	IAR6	IMASK1 and ISR1
PWM Trip Interrupt	IVG10	53	3	IAR6	IMASK1 and ISR1
PWM Sync Interrupt	IVG10	54	3	IAR6	IMASK1 and ISR1
PTP Status Interrupt	IVG10	55	3	IAR6	IMASK1 and ISR1

Event Control

The ADSP-BF512/514/516 processor provides a very flexible mechanism to control the processing of events. In the CEC, three registers are used to coordinate and control events. Each register is 16 bits wide.

- CEC interrupt latch register (ILAT) – Indicates when events have been latched. The appropriate bit is set when the processor has latched the event and cleared when the

event has been accepted into the system. This register is updated automatically by the controller, but it may be written only when its corresponding IMASK bit is cleared.

- CEC interrupt mask register (IMASK) – Controls the masking and unmasking of individual events. When a bit is set in the IMASK register, that event is unmasked and is processed by the CEC when asserted. A cleared bit in the IMASK register masks the event, preventing the processor from servicing the event even though the event may be latched in the ILAT register. This register may be read or written while in supervisor mode. (Note that general-purpose interrupts can be globally enabled and disabled with the STI and CLI instructions, respectively.)
- CEC interrupt pending register (IPEND) – The IPEND register keeps track of all nested events. A set bit in the IPEND register indicates the event is currently active or nested at some level. This register is updated automatically by the controller but may be read while in supervisor mode.

The SIC allows further control of event processing by providing three pairs of 32-bit interrupt control and status registers. Each register contains a bit corresponding to each of the peripheral interrupt events shown in [Table 3 on Page 7](#).

- SIC interrupt mask registers (SIC_IMASK_x) – Control the masking and unmasking of each peripheral interrupt event. When a bit is set in these registers, that peripheral event is unmasked and is processed by the system when asserted. A cleared bit in the register masks the peripheral event, preventing the processor from servicing the event.
- SIC interrupt status registers (SIC_ISR_x) – As multiple peripherals can be mapped to a single event, these registers allow the software to determine which peripheral event source triggered the interrupt. A set bit indicates the peripheral is asserting the interrupt, and a cleared bit indicates the peripheral is not asserting the event.
- SIC interrupt wakeup enable registers (SIC_IWR_x) – By enabling the corresponding bit in these registers, a peripheral can be configured to wake up the processor, should the core be idled when the event is generated. For more information see [Dynamic Power Management on Page 14](#).

Because multiple interrupt sources can map to a single general-purpose interrupt, multiple pulse assertions can occur simultaneously, before or during interrupt processing for an interrupt event already detected on this interrupt input. The IPEND register contents are monitored by the SIC as the interrupt acknowledgement.

The appropriate ILAT register bit is set when an interrupt rising edge is detected (detection requires two core clock cycles). The bit is cleared when the respective IPEND register bit is set. The IPEND bit indicates that the event has entered into the processor pipeline. At this point the CEC recognizes and queues the next rising edge event on the corresponding event input. The minimum latency from the rising edge transition of the general-purpose interrupt to the IPEND output asserted is three core clock cycles; however, the latency can be much higher, depending on the activity within and the state of the processor.

DMA CONTROLLERS

The ADSP-BF512/514/516 processor has multiple, independent DMA channels that support automated data transfers with minimal overhead for the processor core. DMA transfers can occur between the ADSP-BF512/514/516 processor's internal memories and any of its DMA-capable peripherals. Additionally, DMA transfers can be accomplished between any of the DMA-capable peripherals and external devices connected to the external memory interfaces, including the SDRAM controller and the asynchronous memory controller. DMA-capable peripherals include the ethernet MAC, RSI, SPORTs, SPIs, UARTs, and PPI. Each individual DMA-capable peripheral has at least one dedicated DMA channel.

The ADSP-BF512/514/516 processor DMA controller supports both one-dimensional (1-D) and two-dimensional (2-D) DMA transfers. DMA transfer initialization can be implemented from registers or from sets of parameters called descriptor blocks.

The 2-D DMA capability supports arbitrary row and column sizes up to 64K elements by 64K elements, and arbitrary row and column step sizes up to $\pm 32K$ elements. Furthermore, the column step size can be less than the row step size, allowing implementation of interleaved data streams. This feature is especially useful in video applications where data can be deinterleaved on the fly.

Examples of DMA types supported by the ADSP-BF512/514/516 processor DMA controller include:

- A single, linear buffer that stops upon completion
- A circular, auto-refreshing buffer that interrupts on each full or fractionally full buffer
- 1-D or 2-D DMA using a linked list of descriptors
- 2-D DMA using an array of descriptors, specifying only the base DMA address within a common page

In addition to the dedicated peripheral DMA channels, there are two memory DMA channels provided for transfers between the various memories of the ADSP-BF512/514/516 processor system. This enables transfers of blocks of data between any of the memories—including external SDRAM, ROM, SRAM, and flash memory—with minimal processor intervention. Memory DMA transfers can be controlled by a very flexible descriptor-based methodology or by a standard register-based autobuffer mechanism.

The ADSP-BF512/514/516 processor also has an external DMA controller capability via dual external DMA request signals when used in conjunction with the external bus interface unit (EBIU). This functionality can be used when a high speed interface is required for external FIFOs and high bandwidth communications peripherals. It allows control of the number of data transfers for memory DMA. The number of transfers per edge is programmable. This feature can be programmed to allow memory DMA to have an increased priority on the external bus relative to the core.

REAL-TIME CLOCK

The real-time clock (RTC) provides a robust set of digital watch features, including current time, stopwatch, and alarm. The RTC is clocked by a 32.768 kHz crystal external to the ADSP-BF512/514/516 processor. The RTC peripheral has a dedicated power supply so that it can remain powered up and clocked even when the rest of the processor is in a low-power state. The RTC provides several programmable interrupt options, including interrupt per second, minute, hour, or day clock ticks, interrupt on programmable stopwatch countdown, or interrupt at a programmed alarm time.

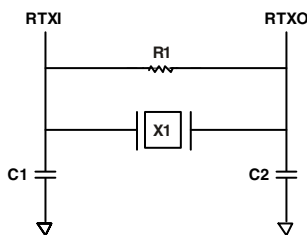
The 32.768 kHz input clock frequency is divided down to a 1 Hz signal by a prescaler. The counter function of the timer consists of four counters: a 60-second counter, a 60-minute counter, a 24-hour counter, and an 32,768-day counter.

When enabled, the alarm function generates an interrupt when the output of the timer matches the programmed value in the alarm control register. There are two alarms: The first alarm is for a time of day. The second alarm is for a day and time of that day.

The stopwatch function counts down from a programmed value, with one-second resolution. When the stopwatch is enabled and the counter underflows, an interrupt is generated.

Like the other peripherals, the RTC can wake up the ADSP-BF512/514/516 processor from sleep mode upon generation of any RTC wakeup event. Additionally, an RTC wakeup event can wake up the ADSP-BF512/514/516 processor from deep sleep mode, and wake up the on-chip internal voltage regulator from the hibernate operating mode.

Connect RTC signals RTXI and RTXO with external components as shown in Figure 3.



SUGGESTED COMPONENTS:

X1 = ECLIPTEK EC38J (THROUGH-HOLE PACKAGE) OR
EPSON MC405 12 pF LOAD (SURFACE-MOUNT PACKAGE)

C1 = 22 pF

C2 = 22 pF

R1 = 10 MΩ

NOTE: C1 AND C2 ARE SPECIFIC TO CRYSTAL SPECIFIED FOR X1. CONTACT CRYSTAL MANUFACTURER FOR DETAILS. C1 AND C2 SPECIFICATIONS ASSUME BOARD TRACE CAPACITANCE OF 3 pF.

Figure 3. External Components for RTC

WATCHDOG TIMER

The ADSP-BF512/514/516 processor includes a 32-bit timer that can be used to implement a software watchdog function. A software watchdog can improve system availability by forcing the processor to a known state through generation of a hard-

ware reset, nonmaskable interrupt (NMI), or general-purpose interrupt, if the timer expires before being reset by software. The programmer initializes the count value of the timer, enables the appropriate interrupt, then enables the timer. Thereafter, the software must reload the counter before it counts to zero from the programmed value. This protects the system from remaining in an unknown state where software, which would normally reset the timer, has stopped running due to an external noise condition or software error.

If configured to generate a hardware reset, the watchdog timer resets both the core and the ADSP-BF512/514/516 processor peripherals. After a reset, software can determine if the watchdog was the source of the hardware reset by interrogating a status bit in the watchdog timer control register.

The timer is clocked by the system clock (SCLK), at a maximum frequency of f_{SCLK} .

TIMERS

There are nine general-purpose programmable timer units in the ADSP-BF512/514/516 processor. Eight timers have an external signal that can be configured either as a pulse width modulator (PWM) or timer output, as an input to clock the timer, or as a mechanism for measuring pulse widths and periods of external events. These timers can be synchronized to an external clock input to the several other associated PF signals, an external clock input to the PPI_CLK input signal, or to the internal SCLK.

The timer units can be used in conjunction with the two UARTs to measure the width of the pulses in the data stream to provide a software auto-baud detect function for the respective serial channels.

The timers can generate interrupts to the processor core providing periodic events for synchronization, either to the system clock or to a count of external signals.

In addition to the eight general-purpose programmable timers, a ninth timer is also provided. This extra timer is clocked by the internal processor clock and is typically used as a system tick clock for generation of operating system periodic interrupts.

3-PHASE PWM

Features of the 3-phase PWM generation unit are:

- 16-bit center-based PWM generation unit
- Programmable PWM pulse width
- Single/double update modes
- Programmable dead time and switching frequency
- Twos-complement implementation which permits smooth transition to full ON and full OFF states
- Possibility to synchronize the PWM generation to an external synchronization
- Special provisions for BDCM operation (crossover and output enable functions)
- Wide variety of special switched reluctance (SR) operating modes

- Output polarity and clock gating control
- Dedicated asynchronous PWM shutdown signal

The ADSP-BF512/514/516 integrates a flexible and program-mable 3-phase PWM waveform generator that can be programmed to generate the required switching patterns to drive a 3-phase voltage source inverter for ac induction (ACIM) or permanent magnet synchronous (PMSM) motor control. In addition, the PWM block contains special functions that considerably simplify the generation of the required PWM switching patterns for control of the electronically commutated motor (ECM) or brushless dc motor (BDCM). Software can enable a special mode for switched reluctance motors (SRM).

The six PWM output signals consist of three high-side drive signals (PWM_AH, PWM_BH, and PWM_CH) and three low-side drive signals (PWM_AL, PWM_BL, and PWM_CL). The polarity of the generated PWM signal be set with software, so that either active HI or active LO PWM patterns can be produced.

The switching frequency of the generated PWM pattern is programmable using the 16-bit PWMTM register. The PWM generator can operate in single update mode or double update mode. In single update mode the duty cycle values are programmable only once per PWM period, so that the resultant PWM patterns are symmetrical about the midpoint of the PWM period. In the double update mode, a second updating of the PWM registers is implemented at the midpoint of the PWM period. In this mode, it is possible to produce asymmetrical PWM patterns that produce lower harmonic distortion in 3-phase PWM inverters.

ROTARY COUNTER

A 32-bit rotary counter is provided that can sense 2-bit quadrature or binary codes as typically emitted by industrial drives or manual thumb wheels. The counter can also operate in general-purpose up/down count modes. Then, count direction is either controlled by a level-sensitive input signal or by two edge detectors.

A third input can provide flexible zero marker support and can alternatively be used to input the push-button signal of thumb wheels. All three signals have a programmable debouncing circuit.

An internal signal forwarded to the timer unit enables one timer to measure the intervals between count events. Boundary registers enable auto-zero operation or simple system warning by interrupts when programmable count values are exceeded.

SERIAL PORTS

The ADSP-BF512/514/516 processor incorporates two dual-channel synchronous serial ports (SPORT0 and SPORT1) for serial and multiprocessor communications. The SPORTs support the following features:

- I²S capable operation.
- Bidirectional operation – Each SPORT has two sets of independent transmit and receive signals, enabling eight channels of I²S stereo audio.

- Buffered (8-deep) transmit and receive ports – Each port has a data register for transferring data words to and from other processor components and shift registers for shifting data in and out of the data registers.
- Clocking – Each transmit and receive port can either use an external serial clock or generate its own, in frequencies ranging from ($f_{SCLK}/131,070$) Hz to ($f_{SCLK}/2$) Hz.
- Word length – Each SPORT supports serial data words from 3 to 32 bits in length, transferred most-significant-bit first or least-significant-bit first.
- Framing – Each transmit and receive port can run with or without frame sync signals for each data word. Frame sync signals can be generated internally or externally, active high or low, and with either of two pulse widths and early or late frame sync.
- Companding in hardware – Each SPORT can perform A-law or μ -law companding according to ITU recommendation G.711. Companding can be selected on the transmit and/or receive channel of the SPORT without additional latencies.
- DMA operations with single-cycle overhead – Each SPORT can automatically receive and transmit multiple buffers of memory data. The processor can link or chain sequences of DMA transfers between a SPORT and memory.
- Interrupts – Each transmit and receive port generates an interrupt upon completing the transfer of a data word or after transferring an entire data buffer, or buffers, through DMA.
- Multichannel capability – Each SPORT supports 128 channels out of a 1024-channel window and is compatible with the H.100, H.110, MVIP-90, and HMVIP standards.

SERIAL PERIPHERAL INTERFACE (SPI) PORTS

The ADSP-BF512/514/516 processor has two SPI-compatible ports (SPI0 and SPI1) that enable the processor to communicate with multiple SPI-compatible devices.

The SPI interface uses three signals for transferring data: two data signals (master output-slave input–MOSI, and master input-slave output–MISO) and a clock signal (serial clock–SCK). An SPI chip select input signal (SPIxSS) lets other SPI devices select the processor, and multiple SPI chip select output signals let the processor select other SPI devices. The SPI select signals are reconfigured general-purpose I/O signals. Using these signals, the SPI port provides a full-duplex, synchronous serial interface, which supports both master/slave modes and multimaster environments.

The SPI port baud rate and clock phase/polarities are programmable, and it has an integrated DMA channel, configurable to support transmit or receive data streams. The SPI's DMA channel can only service unidirectional accesses at any given time.

The SPI port clock rate is calculated as:

$$SPI \text{ Clock Rate} = \frac{f_{SCLK}}{2 \times SPI_BAUD}$$

Where the 16-bit SPI_BAUD register contains a value of 2 to 65,535.

During transfers, the SPI port simultaneously transmits and receives by serially shifting data in and out on its two serial data lines. The serial clock line synchronizes the shifting and sampling of data on the two serial data lines.

UART PORTS

The ADSP-BF512/514/516 processor provides two full-duplex universal asynchronous receiver/transmitter (UART) ports, which are fully compatible with PC-standard UARTs. Each UART port provides a simplified UART interface to other peripherals or hosts, supporting full-duplex, DMA-supported, asynchronous transfers of serial data. A UART port includes support for five to eight data bits, one or two stop bits, and none, even, or odd parity. Each UART port supports two modes of operation:

- PIO (programmed I/O) – The processor sends or receives data by writing or reading I/O mapped UART registers. The data is double-buffered on both transmit and receive.
- DMA (direct memory access) – The DMA controller transfers both transmit and receive data. This reduces the number and frequency of interrupts required to transfer data to and from memory. The UART has two dedicated DMA channels, one for transmit and one for receive. These DMA channels have lower default priority than most DMA channels because of their relatively low service rates.

Each UART port's baud rate, serial data format, error code generation and status, and interrupts are programmable:

- Supporting bit rates ranging from ($f_{SCLK}/1,048,576$) to ($f_{SCLK}/16$) bits per second.
- Supporting data formats from seven to 12 bits per frame.
- Both transmit and receive operations can be configured to generate maskable interrupts to the processor.

The UART port's clock rate is calculated as:

$$\text{UART Clock Rate} = \frac{f_{SCLK}}{16 \times \text{UART_Divisor}}$$

Where the 16-bit UART_Divisor comes from the UART_DLH (most significant 8 bits) and UART_DLL (least significant 8 bits) registers.

In conjunction with the general-purpose timer functions, auto-baud detection is supported.

The capabilities of the UARTs are further extended with support for the infrared data association (IrDA[®]) serial infrared physical layer link specification (SIR) protocol.

TWI CONTROLLER INTERFACE

The ADSP-BF512/514/516 processor includes a two wire interface (TWI) module for providing a simple exchange method of control data between multiple devices. The TWI is compatible with the widely used I²C[®] bus standard. The TWI module offers the capabilities of simultaneous master and slave operation, support for both 7-bit addressing and multimedia data arbitra-

tion. The TWI interface utilizes two signals for transferring clock (SCL) and data (SDA) and supports the protocol at speeds up to 400k bits/sec. The TWI interface signals are compatible with 5 V logic levels.

Additionally, the ADSP-BF512/514/516 processor's TWI module is fully compatible with serial camera control bus (SCCB) functionality for easier control of various CMOS camera sensor devices.

RSI INTERFACE

The removable storage interface (RSI) controller acts as the host interface for multi-media cards (MMC), secure digital memory cards (SD Card), secure digital input/output cards (SDIO), and CE-ATA hard disk drives. The main features of the RSI include:

- Support for a single MMC, SD memory, SDIO card or CE-ATA hard disk drive
- Support for 1-bit and 4-bit SD modes
- Support for 1-bit, 4-bit and 8-bit MMC modes
- Support for 4-bit and 8-bit CE-ATA hard disk drives
- A ten-signal external interface with clock, command, and up to eight data lines
- Card detection using one of the data signals
- Card interface clock generation from SCLK
- SDIO interrupt and read wait features
- CE-ATA command completion signal recognition and disable

10/100 ETHERNET MAC

The ADSP-BF512/514/516 processors offer the capability to directly connect to a network by way of an embedded fast ethernet media access controller (MAC) that supports both 10-BaseT (10M bits/sec) and 100-BaseT (100M bits/sec) operation. The 10/100 ethernet MAC peripheral on the ADSP-BF512/514/516 is fully compliant to the IEEE 802.3-2002 standard and it provides programmable features designed to minimize supervision, bus use, or message processing by the rest of the processor system. A precision time protocol time synchronization engine (PTP_TSYNC) is integrated with the ethernet MAC engine to perform hardware assisted time stamping for IEEE-1588.

Some standard features are:

- Support of MII and RMII protocols for external PHYs
- Full duplex and half duplex modes
- Data framing and encapsulation: generation and detection of preamble, length padding, and FCS
- Media access management (in half-duplex operation): collision and contention handling, including control of retransmission of collision frames and of back-off timing
- Flow control (in full-duplex operation): generation and detection of pause frames
- Station management: generation of MDC/MDIO frames for read-write access to PHY registers

- SCLK operating range down to 25 MHz (active and sleep operating modes)
- Internal loopback from transmit to receive

Some advanced features are:

- Buffered crystal output to external PHY for support of a single crystal system
- Automatic checksum computation of IP header and IP payload fields of Rx frames
- Independent 32-bit descriptor-driven receive and transmit DMA channels
- Frame status delivery to memory through DMA, including frame completion semaphores for efficient buffer queue management in software
- Tx DMA support for separate descriptors for MAC header and payload to eliminate buffer copy operations
- Convenient frame alignment modes support even 32-bit alignment of encapsulated receive or transmit IP packet data in memory after the 14-byte MAC header
- Programmable ethernet event interrupt supports any combination of:
 - Selected receive or transmit frame status conditions
 - PHY interrupt condition
 - Wakeup frame detected
 - Selected MAC management counter(s) at half-full
 - DMA descriptor error
- 47 MAC management statistics counters with selectable clear-on-read behavior and programmable interrupts on half maximum value
- Programmable receive address filters, including a 64-bin address hash table for multicast and/or unicast frames, and programmable filter modes for broadcast, multicast, unicast, control, and damaged frames
- Advanced power management supporting unattended transfer of receive and transmit frames and status to/from external memory via DMA during low-power sleep mode
- System wakeup from sleep operating mode upon magic packet or any of four user-definable wakeup frame filters
- Support for 802.3Q tagged VLAN frames
- Programmable MDC clock rate and preamble suppression
- In RMI operation, seven unused signals may be configured as GPIO signals for other purposes

- Support for IEEE-1588
 - Hardware assisted time stamping via the precision time protocol time synchronization engine (PTP_TSYNC)
 - Clock compensation
 - Programmable message support
 - Dedicated interrupts
 - Alarm feature and time stamp overrun
 - Multiple clock sources (SCLK, MII clock, external clock)

PORTS

Because of the rich set of peripherals, the ADSP-BF512/514/516 processor groups the many peripheral signals to four ports—port F, port G, port H, and port J. Most of the associated pins/balls are shared by multiple signals. The ports function as multiplexer controls. Slew rate and drive strength of the output drivers as well as hysteresis of inputs are programmable.

General-Purpose I/O (GPIO)

The ADSP-BF512/514/516 processor has 40 bidirectional, general-purpose I/O (GPIO) signals allocated across three separate GPIO modules—PORTFIO, PORTGIO, and PORTHIO, associated with Port F, Port G, and Port H, respectively. Port J does not provide GPIO functionality. Each GPIO-capable signal shares functionality with other ADSP-BF512/514/516 processor peripherals via a multiplexing scheme; however, the GPIO functionality is the default state of the device upon power-up. Neither GPIO output nor input drivers are active by default. Each general-purpose port signal can be individually controlled by manipulation of the port control, status, and interrupt registers:

- GPIO direction control register – Specifies the direction of each individual GPIO signal as input or output.
- GPIO control and status registers – The ADSP-BF512/514/516 processor employs a “write one to modify” mechanism that allows any combination of individual GPIO signals to be modified in a single instruction, without affecting the level of any other GPIO signals. Four control registers are provided. One register is written in order to set signal values, one register is written in order to clear signal values, one register is written in order to toggle signal values, and one register is written in order to specify a signal value. Reading the GPIO status register allows software to interrogate the sense of the signals.
- GPIO interrupt mask registers – The two GPIO interrupt mask registers allow each individual GPIO signal to function as an interrupt to the processor. Similar to the two GPIO control registers that are used to set and clear individual signal values, one GPIO interrupt mask register sets bits to enable interrupt function, and the other GPIO interrupt mask register clears bits to disable interrupt function.

GPIO signals defined as inputs can be configured to generate hardware interrupts, while output signals can be triggered by software interrupts.

- GPIO interrupt sensitivity registers – The two GPIO interrupt sensitivity registers specify whether individual signals are level- or edge-sensitive and specify—if edge-sensitive—whether just the rising edge or both the rising and falling edges of the signal are significant. One register selects the type of sensitivity, and one register selects which edges are significant for edge-sensitivity.

PARALLEL PERIPHERAL INTERFACE (PPI)

The ADSP-BF512/514/516 processor provides a parallel peripheral interface (PPI) that can connect directly to parallel A/D and D/A converters, ITU-R-601/656 video encoders and decoders, and other general-purpose peripherals. The PPI consists of a dedicated input clock signal, up to three frame synchronization signals, and up to 16 data signals.

In ITU-R-656 modes, the PPI receives and parses a data stream of 8-bit or 10-bit data elements. On-chip decode of embedded preamble control and synchronization information is supported.

Three distinct ITU-R-656 modes are supported:

- Active video only mode – The PPI does not read in any data between the End of Active Video (EAV) and Start of Active Video (SAV) preamble symbols, or any data present during the vertical blanking intervals. In this mode, the control byte sequences are not stored to memory; they are filtered by the PPI.
- Vertical blanking only mode – The PPI only transfers vertical blanking interval (VBI) data, as well as horizontal blanking information and control byte sequences on VBI lines.
- Entire field mode – The entire incoming bitstream is read in through the PPI. This includes active video, control preamble sequences, and ancillary data that may be embedded in horizontal and vertical blanking intervals.

Though not explicitly supported, ITU-R-656 output functionality can be achieved by setting up the entire frame structure (including active video, blanking, and control information) in memory and streaming the data out the PPI in a frame sync-less mode. The processor's 2-D DMA features facilitate this transfer by allowing the static frame buffer (blanking and control codes) to be placed in memory once, and simply updating the active video information on a per-frame basis.

The general-purpose modes of the PPI are intended to suit a wide variety of data capture and transmission applications. The modes are divided into four main categories, each allowing up to 16 bits of data transfer per PPI_CLK cycle:

- Data receive with internally generated frame syncs
- Data receive with externally generated frame syncs
- Data transmit with internally generated frame syncs
- Data transmit with externally generated frame syncs

These modes support ADC/DAC connections, as well as video communication with hardware signalling. Many of the modes support more than one level of frame synchronization. If desired, a programmable delay can be inserted between assertion of a frame sync and reception/transmission of data.

CODE SECURITY WITH LOCKBOX SECURE TECHNOLOGY

A security system consisting of a blend of hardware and software provides customers with a flexible and rich set of code security features with Lockbox secure technology. Key features include:

- OTP memory
- Unique chip ID
- Code authentication
- Secure mode of operation

The security scheme is based upon the concept of authentication of digital signatures using standards-based algorithms and provides a secure processing environment in which to execute code and protect assets.

DYNAMIC POWER MANAGEMENT

The ADSP-BF512/514/516 processor provides four operating modes, each with a different performance/power profile. In addition, dynamic power management provides the control functions to dynamically alter the processor core supply voltage, further reducing power dissipation. When configured for a 0 volt core supply voltage, the processor enters the hibernate state. Control of clocking to each of the ADSP-BF512/514/516 processor peripherals also reduces power consumption. See [Table 4](#) for a summary of the power settings for each mode.

Full-On Operating Mode—Maximum Performance

In the full-on mode, the PLL is enabled and is not bypassed, providing capability for maximum operational frequency. This is the power-up default execution state in which maximum performance can be achieved. The processor core and all enabled peripherals run at full speed.

Active Operating Mode—Moderate Power Savings

In the active mode, the PLL is enabled but bypassed. Because the PLL is bypassed, the processor's core clock (CCLK) and system clock (SCLK) run at the input clock (CLKIN) frequency. In this mode, the CLKIN to CCLK multiplier ratio can be changed, although the changes are not realized until the full-on mode is entered. DMA access is available to appropriately configured L1 memories.

In the active mode, it is possible to disable the PLL through the PLL control register (PLL_CTL). If disabled, the PLL must be re-enabled before transitioning to the full-on or sleep modes.

Table 4. Power Settings

Mode/State	PLL	PLL Bypassed	Core Clock (CCLK)	System Clock (SCLK)	Core Power
Full On	Enabled	No	Enabled	Enabled	On
Active	Enabled/Disabled	Yes	Enabled	Enabled	On
Sleep	Enabled	—	Disabled	Enabled	On
Deep Sleep	Disabled	—	Disabled	Disabled	On
Hibernate	Disabled	—	Disabled	Disabled	Off

Sleep Operating Mode—High Dynamic Power Savings

The sleep mode reduces dynamic power dissipation by disabling the clock to the processor core (CCLK). The PLL and system clock (SCLK), however, continue to operate in this mode. Typically an external event or RTC activity wakes up the processor. When in the sleep mode, asserting wakeup causes the processor to sense the value of the BYPASS bit in the PLL control register (PLL_CTL). If BYPASS is disabled, the processor transitions to the full on mode. If BYPASS is enabled, the processor transitions to the active mode.

System DMA access to L1 memory is not supported in sleep mode.

Deep Sleep Operating Mode—Maximum Dynamic Power Savings

The deep sleep mode maximizes dynamic power savings by disabling the clocks to the processor core (CCLK) and to all synchronous peripherals (SCLK). Asynchronous peripherals, such as the RTC, may still be running but cannot access internal resources or external memory. This powered-down mode can only be exited by assertion of the reset interrupt ($\overline{\text{RESET}}$) or by an asynchronous interrupt generated by the RTC. When in deep sleep mode, an RTC asynchronous interrupt causes the processor to transition to the Active mode. Assertion of $\overline{\text{RESET}}$ while in deep sleep mode causes the processor to transition to the full on mode.

Hibernate State—Maximum Static Power Savings

The hibernate state maximizes static power savings by disabling the voltage and clocks to the processor core (CCLK) and to all of the synchronous peripherals (SCLK). The internal voltage regulator for the processor can be shut off by writing b#00 to the FREQ bits of the VR_CTL register. This disables both CCLK and SCLK. Furthermore, it sets the internal power supply voltage (V_{DDINT}) to 0 V to provide the lowest static power dissipation. Any critical information stored internally (memory contents, register contents, etc.) must be written to a non-volatile storage device prior to removing power if the processor state is to be preserved.

Since V_{DDEXT} is still supplied in this mode, all of the external signals three-state, unless otherwise specified. This allows other devices that may be connected to the processor to still have power applied without drawing unwanted current.

The ethernet module can wake up the internal supply regulator. If the PF15 pin/ball does not connect as a $\overline{\text{PHYINT}}$ signal to an external PHY device, it can be pulled low by any other device to wake the processor up. The regulator can also be woken up by a real-time clock wakeup event or by asserting the RESET signal. All hibernate wakeup events initiate the hardware reset sequence. Individual sources are enabled by the VR_CTL register.

With the exception of the VR_CTL and the RTC registers, all internal registers and memories lose their content in the hibernate state. State variables may be held in external SRAM or SDRAM. The SCKELOW bit in the VR_CTL register controls whether or not SDRAM operates in self-refresh mode, which allows it to retain its content while the processor is in hibernate and through the subsequent reset sequence.

Power Savings

As shown in Table 5, the ADSP-BF512/514/516 processor supports up to six different power domains, which maximizes flexibility while maintaining compliance with industry standards and conventions. By isolating the internal logic of the ADSP-BF512/514/516 processor into its own power domain, separate from the RTC and other I/O, the processor can take advantage of dynamic power management without affecting the RTC or other I/O devices. There are no sequencing requirements for the various power domains.

Table 5. Power Domains

Power Domain	V_{DD} Range
All internal logic, except RTC, Memory, OTP	V_{DDINT}
RTC internal logic and crystal I/O	V_{DDRTC}
Memory logic	V_{DDMEM}
OTP logic	V_{DDOTP}
Optional internal flash	V_{DDFLASH}
All other I/O	V_{DDEXT}

The dynamic power management feature of the ADSP-BF512/514/516 processor allows both the processor’s input voltage (V_{DDINT}) and clock frequency (f_{CCLK}) to be dynamically controlled.

The power dissipated by a processor is largely a function of its clock frequency and the square of the operating voltage. For example, reducing the clock frequency by 25% results in a 25% reduction in dynamic power dissipation, while reducing the voltage by 25% reduces dynamic power dissipation by more than 40%. Further, these power savings are additive, in that if the clock frequency and supply voltage are both reduced, the power savings can be dramatic, as shown in the following equations.

Power Savings Factor

$$= \frac{f_{CCLKRED}}{f_{CCLKNOM}} \times \left(\frac{V_{DDINTRED}}{V_{DDINTNOM}} \right)^2 \times \left(\frac{T_{RED}}{T_{NOM}} \right)$$

$$\% \text{ Power Savings} = (1 - \text{Power Savings Factor}) \times 100\%$$

where the variables in the equations are:

$f_{CCLKNOM}$ is the nominal core clock frequency

$f_{CCLKRED}$ is the reduced core clock frequency

$V_{DDINTNOM}$ is the nominal internal supply voltage

$V_{DDINTRED}$ is the reduced internal supply voltage

T_{NOM} is the duration running at $f_{CCLKNOM}$

T_{RED} is the duration running at $f_{CCLKRED}$

VOLTAGE REGULATION

The processor provides an on-chip voltage regulator that can generate processor core voltage levels from an external supply. Figure 4 shows the typical external components required to complete the power management system. The regulator controls the internal logic voltage levels and is programmable with the voltage regulator control register (VR_CTL) in increments of 50 mV. To reduce standby power consumption, the internal voltage regulator can be programmed to remove power to the processor core while keeping I/O power supplied. While in the hibernate state, V_{DDEXT} can still be applied, eliminating the need for external buffers. The voltage regulator can be activated from this power down state either through an RTC wakeup, an ethernet wakeup, or by asserting the \overline{RESET} signal or by other peripheral wakeup events, each of which then initiates a boot sequence. The regulator can also be disabled and bypassed at the user's discretion.

The voltage regulator has two modes set by the VRSEL signal—the normal pulse width control of an external FET and the external supply mode which can signal a power down during hibernate to an external regulator. Set VRSEL to V_{DDEXT} to use an external regulator or set VRSEL to GND to use the internal regulator. In the external mode VROUT becomes EXT_WAKE. If the internal regulator is used, another EXT_WAKE signal can control other power sources in the system during the hibernate operating mode. Both signals are high-true for power-up and may be connected directly to the low-true shut down input of many common regulators. The (Soft Start/Power Good indication) signal is a new feature in the ADSP-BF512/514/516 processors. The mode of this signal changes from SS to \overline{PG} according to the state of the VRSEL signal. When using an internal regulator the SS/ \overline{PG} signal is Soft Start and when using an external regulator it is Power Good. For

a complete description of Soft Start and Power Good functionality refer to the ADSP-BF512/514/516 Blackfin Processor Hardware Reference.

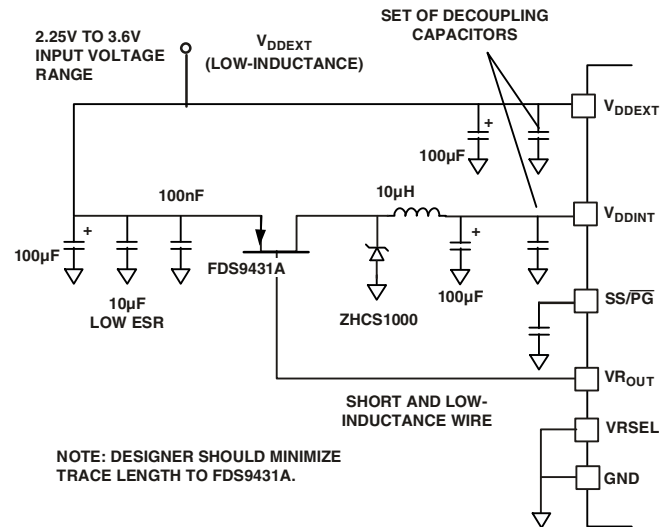


Figure 4. Voltage Regulator Circuit

CLOCK SIGNALS

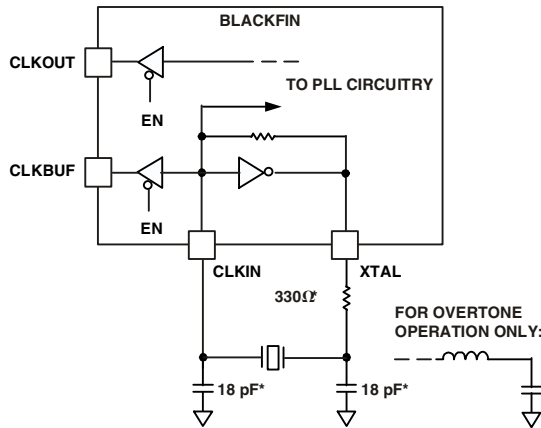
The ADSP-BF512/514/516 processor can be clocked by an external crystal, a sine wave input, or a buffered, shaped clock derived from an external clock oscillator.

If an external clock is used, it should be a TTL compatible signal and must not be halted, changed, or operated below the specified frequency during normal operation. This signal is connected to the processor CLKIN signal. When an external clock is used, the XTAL pin/ball must be left unconnected.

Alternatively, because the ADSP-BF512/514/516 processor includes an on-chip oscillator circuit, an external crystal may be used. For fundamental frequency operation, use the circuit shown in Figure 5. A parallel-resonant, fundamental frequency, microprocessor-grade crystal is connected across the CLKIN and XTAL pins/balls. The on-chip resistance between the CLKIN pin/ball and the XTAL pin/ball is in the 500 kΩ range. Further parallel resistors are typically not recommended. The two capacitors and the series resistor shown in Figure 5 fine tune phase and amplitude of the sine frequency.

The capacitor and resistor values shown in Figure 5 are typical values only. The capacitor values are dependent upon the crystal manufacturers' load capacitance recommendations and the PCB physical layout. The resistor value depends on the drive level

specified by the crystal manufacturer. The user should verify the customized values based on careful investigations on multiple devices over temperature range.



NOTE: VALUES MARKED WITH * MUST BE CUSTOMIZED DEPENDING ON THE CRYSTAL AND LAYOUT. PLEASE ANALYZE CAREFULLY.

Figure 5. External Crystal Connections

A third-overtone crystal can be used for frequencies above 25 MHz. The circuit is then modified to ensure crystal operation only at the third overtone, by adding a tuned inductor circuit as shown in Figure 5. A design procedure for third-overtone operation is discussed in detail in application note (EE-168) Using Third Overtone Crystals with the ADSP-218x DSP on the Analog Devices website (www.analog.com)—use site search on “EE-168.”

The CLKBUF signal is an output signal, which is a buffered version of the input clock. This signal is particularly useful in ethernet applications to limit the number of required clock sources in the system. In this type of application, a single 25 MHz or 50 MHz crystal may be applied directly to the ADSP-BF512/514/516 processor. The 25 MHz or 50 MHz output of CLKBUF can then be connected to an external ethernet MII or RMII PHY device.

The Blackfin core runs at a different clock rate than the on-chip peripherals. As shown in Figure 6, the core clock (CCLK) and system peripheral clock (SCLK) are derived from the input clock (CLKIN) signal. An on-chip PLL is capable of multiplying the CLKIN signal by a programmable 0.5x to 64x multiplication factor (bounded by specified minimum and maximum VCO frequencies). The default multiplier is 5x, but it can be modified by a software instruction sequence.

On-the-fly frequency changes can be effected by simply writing to the PLL_DIV register. The maximum allowed CCLK and SCLK rates depend on the applied voltages V_{DDINT} and V_{DDEXT} ; the VCO is always permitted to run up to the frequency specified by the part’s speed grade. The CLKOUT signal reflects the SCLK frequency to the off-chip world. It belongs to the SDRAM

interface, but it functions as reference signal in other timing specifications as well. While active by default, it can be disabled using the EBIU_SDGCTL and EBIU_AMGCTL registers.

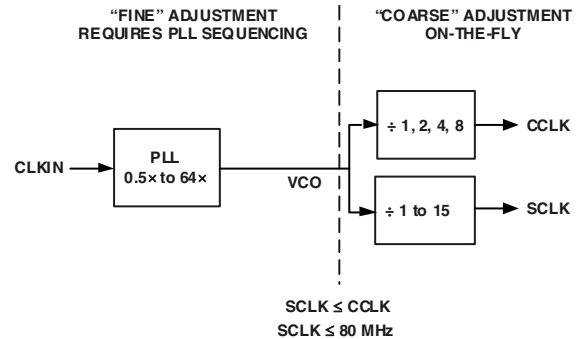


Figure 6. Frequency Modification Methods

All on-chip peripherals are clocked by the system clock (SCLK). The system clock frequency is programmable by means of the SSEL3–0 bits of the PLL_DIV register. The values programmed into the SSEL fields define a divide ratio between the PLL output (VCO) and the system clock. SCLK divider values are 1 through 15. Table 6 illustrates typical system clock ratios.

Note that the divisor ratio must be chosen to limit the system clock frequency to its maximum of f_{SCLK} . The SSEL value can be changed dynamically without any PLL lock latencies by writing the appropriate values to the PLL divisor register (PLL_DIV).

Table 6. Example System Clock Ratios

Signal Name SSEL3–0	Divider Ratio VCO/SCLK	Example Frequency Ratios (MHz)	
		VCO	SCLK
0001	1:1	50	50
0110	6:1	300	50
1010	10:1	400	40

The core clock (CCLK) frequency can also be dynamically changed by means of the CSEL1–0 bits of the PLL_DIV register. Supported CCLK divider ratios are 1, 2, 4, and 8, as shown in Table 7. This programmable core clock capability is useful for fast core frequency modifications.

Table 7. Core Clock Ratios

Signal Name CSEL1–0	Divider Ratio VCO/CCLK	Example Frequency Ratios (MHz)	
		VCO	CCLK
00	1:1	300	300
01	2:1	300	150
10	4:1	400	100
11	8:1	200	25

The maximum CCLK frequency not only depends on the part's speed grade (see Page 64), it also depends on the applied V_{DDINT} voltage. See Table 13 for details. The maximal system clock rate (SCLK) depends on the chip package and the applied V_{DDEXT} voltage (see Table 16 on Page 26).

BOOTING MODES

The processor has several mechanisms (listed in Table 8) for automatically loading internal and external memory after a reset. The boot mode is defined by three BMODE input bits dedicated to this purpose. There are two categories of boot modes. In master boot modes the processor actively loads data from parallel or serial memories. In slave boot modes the processor receives data from external host devices.

The boot modes listed in Table 8 provide a number of mechanisms for automatically loading the processor's internal and external memories after a reset. By default, all boot modes use the slowest meaningful configuration settings. Default settings can be altered via the initialization code feature at boot time or by proper OTP programming at pre-boot time. The BMODE bits of the reset configuration register, sampled during power-on resets and software-initiated resets, implement the modes shown in Table 8.

Table 8. Booting Modes

BMODE2-0	Description
000	Idle - No boot
001	Boot from 8- or 16-bit external flash memory
010	Boot from internal SPI memory
011	Boot from external SPI memory (EEPROM or flash)
100	Boot from SPI0 host
101	Boot from OTP memory
110	Boot from SDRAM
111	Boot from UART0 Host

- Idle/no boot mode (BMODE = 0x0) — In this mode, the processor goes into idle. The idle boot mode helps recover from illegal operating modes, such as when the user has misconfigured the OTP memory.
- Boot from 8-bit or 16-bit external flash memory (BMODE = 0x1) — In this mode, the boot kernel loads the first block header from address 0x2000 0000 and—depending on instructions containing in the header—the boot kernel performs 8-bit or 16-bit boot or starts program execution at the address provided by the header. By default, all configuration settings are set for the slowest device possible (3-cycle hold time, 15-cycle R/W access times, 4-cycle setup).

The ARDY is not enabled by default, but it can be enabled by OTP programming. Similarly, all interface behavior and timings can be customized by OTP programming. This includes activation of burst-mode or page-mode operation. In this mode, all signals belonging to the asynchronous interface are enabled at the port muxing level.

- Boot from internal SPI memory (BMODE = 0x2) — The processor uses SPI0 to load from code previously loaded to the 4 Mbit internal SPI flash. Only available on the ADSP-BF512F/ADSP-BF514F/ADSP-BF516F.
- Boot from external SPI EEPROM or flash (BMODE = 0x3) — 8-bit, 16-bit, 24-bit or 32-bit addressable devices are supported. The processor uses the PG15 GPIO signal to select a single SPI EEPROM/flash device connected to the SPI0 interface; then submits a read command and successive address bytes (0x00) until a valid 8-, 16-, 24-, or 32-bit addressable device is detected. Pull-up resistors are required on the SSEL and MISO signals. By default, a value of 0x85 is written to the SPI0_BAUD register.
- Boot from SPI0 host device (BMODE = 0x4) — The processor operates in SPI slave mode and is configured to receive the bytes of the LDR file from an SPI host (master) agent. In the host, the HWAIT signal must be interrogated by the host before every transmitted byte. A pull-up resistor is required on the $\overline{SPI0SS}$ input. A pull-down on the serial clock may improve signal quality and booting robustness.
- Boot from OTP memory (BMODE = 0x5) — This provides a stand-alone booting method. The boot stream is loaded from on-chip OTP memory. By default the boot stream is expected to start from OTP page 0x40 on and can occupy all public OTP memory up to page 0xDF. This is 2560 bytes. Since the start page is programmable the maximum size of the boot stream can be extended to 3072 bytes.
- Boot from SDRAM (BMODE = 0x6) This is a warm boot scenario, where the boot kernel starts booting from address 0x0000 0010. The SDRAM is expected to contain a valid boot stream and the SDRAM controller must be configured by the OTP settings.
- Boot from UART0 host (BMODE = 0x7) — Using an auto-baud handshake sequence, a boot-stream formatted program is downloaded by the host. The host selects a bit rate within the UART clocking capabilities.

When performing the autobaud, the UART expects a “@” (0x40) character (eight bits data, one start bit, one stop bit, no parity bit) on the RX0 signal to determine the bit rate. The UART then replies with an acknowledgement composed of 4 bytes (0xBF—the value of UART0_DLL and 0x00—the value of UART0_DLH). The host can then download the boot stream. To hold off the host the Blackfin processor signals the host with the boot host wait (HWAIT) signal. Therefore, the host must monitor HWAIT before every transmitted byte.

For each of the boot modes, a 16-byte header is first read from an external memory device. The header specifies the number of bytes to be transferred and the memory destination address. Multiple memory blocks may be loaded by any boot sequence. Once all blocks are loaded, program execution commences from the address stored in the EVT1 register.

Prior to booting, the pre-boot routine interrogates the OTP memory. Individual boot modes can be customized or even disabled based on OTP programming. External hardware,

especially booting hosts may watch the HWAIT signal to determine when the pre-boot has finished and the boot kernel starts the boot process. By programming OTP memory, the user can instruct the preboot routine to also customize: PLL and Voltage Regulator; SDRAM Controller; and Asynchronous Interface.

The boot kernel differentiates between a regular hardware reset and a wakeup-from-hibernate event to speed up booting in the later case. Bits 6-4 in the system reset configuration (SYSCR) register can be used to bypass pre-boot routine and/or boot kernel in case of a software reset. They can also be used to simulate a wakeup-from-hibernate boot in the software reset case.

The boot process can be further customized by “initialization code.” This is a piece of code that is loaded and executed prior to the regular application boot. Typically, this is used to configure the SDRAM controller or to speed up booting by managing PLL, clock frequencies, wait states, or serial bit rates.

The boot ROM also features C-callable function entries that can be called by the user application at run time. This enables second-stage boot or boot management schemes to be implemented with ease.

INSTRUCTION SET DESCRIPTION

The Blackfin processor family assembly language instruction set employs an algebraic syntax designed for ease of coding and readability. The instructions have been specifically tuned to provide a flexible, densely encoded instruction set that compiles to a very small final memory size. The instruction set also provides fully featured multifunction instructions that allow the programmer to use many of the processor core resources in a single instruction. Coupled with many features more often seen on microcontrollers, this instruction set is very efficient when compiling C and C++ source code. In addition, the architecture supports both user (algorithm/application code) and supervisor (O/S kernel, device drivers, debuggers, ISRs) modes of operation, allowing multiple levels of access to core processor resources.

The assembly language, which takes advantage of the processor’s unique architecture, offers the following advantages:

- Seamlessly integrated DSP/MCU features are optimized for both 8-bit and 16-bit operations.
- A multi-issue load/store modified-harvard architecture, which supports two 16-bit MACs or four 8-bit ALUs plus two load/store plus two pointer updates per cycle.
- All registers, I/O, and memory are mapped into a unified 4G byte memory space, providing a simplified programming model.
- Microcontroller features, such as arbitrary bit and bit-field manipulation, insertion, and extraction; integer operations on 8-, 16-, and 32-bit data-types; and separate user and supervisor stack pointers.
- Code density enhancements, which include intermixing of 16-bit and 32-bit instructions (no mode switching, no code segregation). Frequently used instructions are encoded in 16 bits.

DEVELOPMENT TOOLS

The ADSP-BF512/514/516 processor is supported with a complete set of CROSSCORE® software and hardware development tools, including Analog Devices emulators and VisualDSP++® development environment. The same emulator hardware that supports other Blackfin processors also fully emulates the ADSP-BF512/514/516 processor.

EZ-KIT Lite Evaluation Board

For evaluation of ADSP-BF512/514/516 processors, use the EZ-KIT Lite® board being developed by Analog Devices. The board comes with on-chip emulation capabilities and is equipped to enable software development. Multiple daughter cards are available.

DESIGNING AN EMULATOR-COMPATIBLE PROCESSOR BOARD (TARGET)

The Analog Devices family of emulators are tools that every system developer needs in order to test and debug hardware and software systems. Analog Devices has supplied an IEEE 1149.1 JTAG Test Access Port (TAP) on each JTAG processor. The emulator uses the TAP to access the internal features of the processor, allowing the developer to load code, set breakpoints, observe variables, observe memory, and examine registers. The processor must be halted to send data and commands, but once an operation has been completed by the emulator, the processor system is set running at full speed with no impact on system timing.

To use these emulators, the target board must include a header that connects the processor’s JTAG port to the emulator.

For details on target board design issues including mechanical layout, single processor connections, multiprocessor scan chains, signal buffering, signal termination, and emulator pod logic, see (EE-68) *Analog Devices JTAG Emulation Technical Reference* on the Analog Devices website (www.analog.com)—use site search on “EE-68.” This document is updated regularly to keep pace with improvements to emulator support.

RELATED DOCUMENTS

The following publications that describe the ADSP-BF512/514/516 processors (and related processors) can be ordered from any Analog Devices sales office or accessed electronically on our website:

- *Getting Started With Blackfin Processors*
- *ADSP-BF512/514/516 Blackfin Processor Hardware Reference*
- *ADSP-BF53x/BF56x Blackfin Processor Programming Reference*
- *ADSP-BF512/514/516 Blackfin Processor Anomaly List*

SIGNAL DESCRIPTIONS

ADSP-BF512/514/516 processor signal definitions are listed in Table 9. In order to maintain maximum function and reduce package size and signal count, some signals have dual, multiplexed functions. In cases where signal function is reconfigurable, the default state is shown in plain text, while the alternate function is shown in italics.

All signals are three-stated during and immediately after reset, with the exception of the external memory interface and the buffered XTAL output signal, (CLKBUF). On the external memory interface, the control and address lines are driven high during reset.

All I/O signals have their input buffers disabled with the exception of the signals noted in the data sheet that need pull-ups or pull downs if unused.

The SDA (serial data) and SCL (serial clock) pins/balls are open drain and therefore require a pullup resistor. Consult version 2.1 of the I²C specification for the proper resistor value.

Table 9. Signal Descriptions

Signal Name	Type	Function	Driver Type ¹
<i>EBIU</i>			
ADDR19–1	O	Address Bus	
DATA15–0	I/O	Data Bus	
<i>ABE1–0/SDQM1–0</i>	O	Byte Enable or Data Mask	
<i>AMS1–0</i>	O	Bank Select	
<i>ARE</i>	O	Asynchronous Memory Read Enable	
<i>AWE</i>	O	Write Enable for Async	
<i>SRAS</i>	O	SDRAM Row Address Strobe	
<i>SCAS</i>	O	SDRAM Column Address Strobe	
<i>SWE</i>	O	SDRAM Write Enable	
SCKE	O	SDRAM Clock Enable	
CLKOUT	O	SDRAM Clock Output	
SA10	O	SDRAM A10 Signal	
<i>SMS</i>	O	SDRAM Bank Select	
<i>Port F: GPIO and Multiplexed Peripherals</i>			
PF0/ <i>ETxD2/PPI D0/SPI1_SSEL2/TACLK6</i>	I/O	GPIO/Ethernet MII Transmit D2/PPI Data 0/SPI1 Slave Select 2/Timer6 Alternate Clock	
PF1/ <i>ERxD2/PPI D1/PWM AH/TACLK7</i>	I/O	GPIO/Ethernet MII Receive D2/PPI Data 1/PWM AH Output/Timer7 Alternate Clock	
PF2/ <i>ETxD3/PPI D2/PWM AL</i>	I/O	GPIO/Ethernet Transmit D3/PPI Data 2/PWM AL Output	
PF3/ <i>ERxD3/PPI D3/PWM BH/TACLK0</i>	I/O	GPIO/Ethernet MII Data Receive D3/PPI Data 3/PWM BH Output/Timer0 Alternate Clock	
PF4/ <i>ERxCLK/PPI D4/PWM BL/TACLK1</i>	I/O	GPIO/Ethernet MII Receive Clock/PPI Data 4/PWM BL Out/Timer1 Alternate CLK	
PF5/ <i>ERxDV/PPI D5/PWM CH/TACIO</i>	I/O	GPIO/Ethernet MII or RMII Receive Data Valid/PPI Data 5/PWM CH Out /Timer0 Alternate Capture Input	
PF6/ <i>COL/PPI D6/PWM CL/TACI1</i>	I/O	GPIO/Ethernet MII Collision/PPI Data 6/PWM CL Out/Timer1 Alternate Capture Input	
PF7/ <i>SPI0_SSEL1/PPI D7/PWM_SYNC</i>	I/O	GPIO/SPI0 Slave Select 1/PPI Data 7/PWM Sync	
PF8/ <i>MDC/PPI D8/SPI1_SSEL4</i>	I/O	GPIO/Ethernet Management Channel Clock/PPI Data 8/SPI1 Slave Select 4	
PF9/ <i>RMIIMDIO/PPI D9/TMR2</i>	I/O	GPIO/Ethernet Management Channel Serial Data/PPI Data 9/Timer 2	
PF10/ <i>ETxD0/PPI D10/TMR3</i>	I/O	GPIO/Ethernet MII or RMII Transmit D0/PPI Data 10/Timer 3	
PF11/ <i>ERxD0/PPI D11/PWM AH/TACI3</i>	I/O	GPIO/Ethernet MII Receive D0/PPI Data 11/PWM AH output /Timer3 Alternate Capture Input	

Table 9. Signal Descriptions

Signal Name	Type	Function	Driver Type ¹
PF12/ETxD1/PPI D12/PWM AL	I/O	GPIO/Ethernet MII Transmit D1/PPI Data 12/PWM AL Output	
PF13/ERxD1/PPI D13/PWM BH	I/O	GPIO/Ethernet MII or RMI Receive D1/PPI Data 13/PWM BH Output	
PF14/ETxEN/PPI D14/PWM BL	I/O	GPIO/Ethernet MII Transmit Enable/PPI Data 14/PWM BL Out	
PF15 ² /RMII PHYINT/PPI D15/PWM_SYNC	I/O	GPIO/Ethernet MII PHY Interrupt/PPI Data 15/PWM Sync	
<i>Port G: GPIO and Multiplexed Peripherals</i>			
PG0/MIICRS/RMIICRS/HWAIT ³ /SPI1_SSEL3	I/O	GPIO/Ethernet MII or RMI Carrier Sense/HWAIT/SPI1 Slave Select3	
PG1/ERxER/DMAR1/PWM CH	I/O	GPIO/Ethernet MII or RMI Receive Error/DMA Req 1/PWM CH Out	
PG2/MIITxCLK/RMIIREF_CLK/DMAR0/PWM CL	I/O	GPIO/Ethernet MII or RMI Reference Clock/DMA Req 0/PWM CL Out	
PG3/DR0PRI/RSI_DATA0/SPI0_SSEL5/TACLK3	I/O	GPIO/SPORT0 Primary Rx Data/RSI Data 0/SPI0 Slave Select 5/Timer3 Alternate CLK	
PG4/RSCLK0/RSI_DATA1/TMR5/TACI5	I/O	GPIO/SPORT0 Rx Clock/RSI Data 1/Timer 5/Timer5 Alternate Capture Input	
PG5/RFS0/RSI_DATA2/PPICLK/TMRCLK	I/O	GPIO/SPORT0 Rx Frame Sync/RSI Data 2/PPI Clock/External Timer Reference	
PG6/TFS0/RSI_DATA3/TMR0/PPIFS1	I/O	GPIO/SPORT0 Tx Frame Sync/RSI Data 3/Timer0/PPI Frame Sync1	
PG7/DT0PRI/RSI_CMD/TMR1/PPIFS2	I/O	GPIO/SPORT0 Tx Primary Data/RSI Command/Timer 1/PPI Frame Sync2	
PG8/TSCLK0/RSI_CLK/TMR6/TACI6	I/O	GPIO/SPORT0 Tx Clock/RSI Clock/Timer 6/Timer6 Alternate Capture Input	
PG9/DT0SEC/UART0 TX/TMR4	I/O	GPIO/SPORT0 Secondary Tx Data/Uart0 Transmit/Timer 4	
PG10/DR0SEC/UART0 RX/TACI4	I/O	GPIO/SPORT0 Secondary Rx Data/Uart0 Receive/Timer4 Alternate Capture Input	
PG11/SPI0_SS/AMS[2]/SPI1_SSEL5/TACLK2	I/O	GPIO/SPI0 Slave Device Select/Asynchronous Memory Bank Select 2/SPI1 Slave Select 5 /Timer2 Alternate CLK	
PG12/SPI0_SCK/PPICLK/TMRCLK	I/O	GPIO/SPI0 Clock/PPI Clock/External Timer Reference	
PG13/SPI0_MISO ⁴ /TMR0/PPIFS1	I/O	GPIO/SPI0 Master In Slave Out/Timer0/PPI Frame Sync1	
PG14/SPI0_MOSI/TMR1/PPIFS2/PWM_TRIPB	I/O	GPIO/SPI0 Master Out Slave In/Timer 1/PPI Frame Sync2/PWM Trip	
PG15/SPI0_SSEL2/PPIFS3/AMS[3]	I/O	GPIO/SPI0 Slave Select 2/PPI Frame Sync3/Asynchronous Memory Bank Select 3	
<i>Port H: GPIO and Multiplexed Peripherals</i>			
PH0/DR1PRI/SPI1_SS/RSI_DATA4	I/O	GPIO/SPORT1 Primary Rx Data/SPI1 Device Select/RSI Data 4	
PH1/RFS1/SPI1_MISO/RSI_DATA5	I/O	GPIO/SPORT1 Rx Frame Sync/SPI1 Master In Slave Out/RSI Data 5	
PH2/RSCLK1/SPI1_SCK/RSI DATA6	I/O	GPIO/SPORT1 Rx Clock/SPI1 Clock/RSI Data 6	
PH3/DT1PRI/SPI1_MOSI/RSI DATA7	I/O	GPIO/SPORT1 Primary Tx Data/SPI1 Master Out Slave In/RSI Data 7	
PH4/TFS1/AOE/SPI0_SSEL3/CUD	I/O	GPIO/SPORT1 Tx Frame Sync/Asynchronous Memory Output Enable/SPI0 Slave Select 3 /Counter Up Direction	
PH5/TSCLK1/ARDY/ECLK/CDG	I/O	GPIO/SPORT1 Tx Clock/Asynchronous Memory Hardware Ready Control /External Clock for PTP TSYNC/Counter Down Gate	
PH6/DT1SEC/UART1 TX/SPI1_SSEL1/CZM	I/O	GPIO/SPORT1 Secondary Tx Data/Uart1 Transmit/SPI1 Slave Select 1 /Counter Zero Marker	
PH7/DR1SEC/UART1 RX/TMR7/TACI2	I/O	GPIO/SPORT1 Secondary Rx Data/Uart1 Receive/Timer 7/Timer2 Alternate Clock Input	
<i>Port J</i>			
PJ0:SCL	I/O 5V	TWI Serial Clock	
PJ1:SDA	I/O 5V	TWI Serial Data	
<i>Real Time Clock</i>			
RTXI	I	RTC Crystal Input	
RTXO	O	RTC Crystal Output	

Table 9. Signal Descriptions

Signal Name	Type	Function	Driver Type ¹
<i>JTAG Port</i>			
TCK	I	JTAG Clock	
TDO	O	JTAG Serial Data Out	
TDI	I	JTAG Serial Data In	
TMS	I	JTAG Mode Select	
$\overline{\text{TRST}}$	I	JTAG Reset	
$\overline{\text{EMU}}$	O	Emulation Output	
<i>Clock</i>			
CLKIN	I	Clock/Crystal Input	
XTAL	O	Crystal Output	
CLKBUF	O	Buffered XTAL Output	
<i>Mode Controls</i>			
$\overline{\text{RESET}}$	I	Reset	
$\overline{\text{NMI}}$	I	Non-maskable Interrupt	
BMODE2-0	I	Boot Mode Strap 2-0	
<i>Voltage Regulator</i>			
VROUT	O	External FET Drive	
VRSEL	I	External/Internal Voltage Regulator Select	
$\text{SS}/\overline{\text{PG}}$	I	Soft Start/PwrGood	
EXT_WAKE	O	Wake-up Indication	
<i>Power Supplies</i>			
V _{DDEXT}	P	I/O Power Supply	
V _{DDINT}	P	Internal Power Supply (regulated from 2.25 V to 3.6 V)	
V _{DDRTC}	P	Real Time Clock Power Supply	
V _{DDFLASH}	P	Internal SPI Flash Power Supply	
V _{PPOTP}	P	MEM Power Supply	
V _{DDMEM}	P	OTP Power Supply	
V _{DDOTP}	P	OTP Programming Voltage	
V _{SS}	G	Ground for All Supplies	

¹ See [Output Drive Currents on Page 48](#) for more information about each driver type.

² When driven low, the PF15 signal can be used to wake up the processor from the hibernate state, either in normal GPIO mode or in ethernet mode as $\overline{\text{PHYINT}}$. If the pin/ball is used for wake up, enable the feature with the PHYWE bit in the VR_CTL register, and pull-up the signal with a resistor.

³ Boot host wait is a GPIO signal toggled by the boot kernel. The mandatory external pull-up/pull-down resistor defines the signal polarity.

⁴ A pull-up resistor is required for the boot from external SPI EEPROM or flash (BMODE = 0x3).

SPECIFICATIONS

Note that component specifications are subject to change without notice.

OPERATING CONDITIONS

Parameter	Conditions	Min	Nominal	Max	Unit
V _{DDINT}	Internal Supply Voltage ¹	tbd	tbd	tbd	V
V _{DDEXT} ²	External Supply Voltage ³	1.75	1.8 ⁴ , 2.5 or 3.3	3.6	V
V _{DDRTC} ⁵	Real Time Clock Power Supply Voltage	2.25		3.6	V
V _{DDMEM} ⁶	MEM Supply Voltage ²	1.75	1.8, 2.5 or 3.3	3.6	V
V _{DDFLASH}	Internal SPI Flash Supply Voltage	1.65	1.8	1.95	V
V _{DDOTP}	OTP Supply Voltage ²	2.25	2.5	2.75	V
V _{PPOTP}	OTP Programming Voltage				
	For Reads ²	2.25	2.5	2.75	V
	For Writes ⁷	6.9	7.0	7.1	V
V _{IH}	High Level Input Voltage ^{8,9}	V _{DDEXT} = maximum		3.6	V
V _{IHCLKIN}	High Level Input Voltage ¹⁰	V _{DDEXT} = maximum		3.6	V
V _{IHSV}	High Level Input Voltage ¹¹	V _{DDEXT} = maximum		5.5	V
V _{IL}	Low Level Input Voltage ^{11,13}	V _{DDEXT} = minimum		+0.6	V
V _{ILSV}	Low Level Input Voltage ¹¹	V _{DDEXT} = minimum		+0.8	V
T _J	Junction Temperature	tbd-Ball CSP_BGA @ T _{AMBIENT} = 0°C to +70°C		+105	°C

¹ The voltage regulator can generate V_{DDINT} at levels of tbd V to tbd V with tbd% to +tbd% tolerance.

² Must remain powered (even if the associated function is not used).

³ V_{DDEXT} is the supply to the voltage regulator and GPIO. If the voltage regulator is not being used, the VROUT signal should be tied to one of the I/O supplies.

⁴ 1.8 V does not apply for the voltage regulator.

⁵ If not used, power with V_{DDEXT}.

⁶ Pins/balls that use V_{DDMEM} are DATA15-0, ADDR19-1, ABE1-0, ARE, AWE, AMS1-0, SA10, SWE, SCAS, CLKOUT, SRAS, SMS, SCCKE. These pins/balls are not tolerant to voltages higher than V_{DDMEM}. When using any of the asynchronous memory signals AMS3-2, ARDY, or AOE V_{DDMEM} and V_{DDEXT} must be shorted externally because these signals are multiplexed with GPIO.

⁷ The V_{DDOTP} voltage for writes must only be applied when programming OTP memory. There is a finite amount of cumulative time that this voltage may be applied (dependent on voltage and junction temperature) over the lifetime of the part. Please see Table 11 on Page 25 for details.

⁸ Bidirectional pins/balls (PF15-0, PG15-0, PH7-0) and input pins/balls (RTXI, TCK, TDI, TMS, TRST, CLKIN, RESET, NMI, and BMODE2-0) of the ADSP-BF512/514/516 are 3.3 V tolerant (always accept up to 3.6 V maximum V_{IH}). Voltage compliance (on outputs, V_{OH}) is limited by the V_{DDEXT} supply voltage.

⁹ Parameter value applies to all input and bidirectional pins/balls except CLKIN, SDA, and SCL.

¹⁰ Parameter value applies to CLKIN pin/ball only.

¹¹ Pins/balls SDA and SCL are 5.0 V tolerant (always accept up to 5.5 V maximum V_{IH}). Voltage compliance on outputs (V_{OH}) is limited by the V_{DDEXT} supply voltage.

¹² SDA and SCL are pulled up to V_{BUS}.

¹³ Parameter value applies to all input and bidirectional pins/balls except SDA and SCL.

ELECTRICAL CHARACTERISTICS

Parameter	Test Conditions	Min	Typical	Max	Unit
V _{OH}	High Level Output Voltage (All Outputs and I/Os Except Port F, Port G, Port H)	TBD			V
	V _{DDEXT} = 3.3 V ± 10%, I _{OH} = 0.5 mA V _{DDEXT} = 2.5 V ± 10%, I _{OH} = 0.5 mA				
V _{OH}	High Level Output Voltage (Port F, Port G, Port H) —Low Drive Strength	TBD			V
	V _{DDEXT} = 3.3 V ± 10%, I _{OH} = TBD mA V _{DDEXT} = 2.5 V ± 10%, I _{OH} = TBD mA V _{DDEXT} = 1.8 V ± 10%, I _{OH} = TBD mA				
V _{OH}	High Level Output Voltage (Port F, Port G, Port H) —High Drive Strength	TBD			V
	V _{DDEXT} = 3.3 V ± 10%, I _{OH} = TBD mA V _{DDEXT} = 2.5 V ± 10%, I _{OH} = TBD mA V _{DDEXT} = 1.8 V ± 10%, I _{OH} = TBD mA				
I _{OH}	High Level Output Current (Maximum Combined for Port F7–0)			TBD	mA
	V _{OH} = V _{DDEXT} – 0.5 V min				
I _{OH}	High Level Output Current (Maximum Total for all Port F, Port G, and Port H pins/balls)			TBD	mA
	V _{OH} = V _{DDEXT} – 0.5 V min				
V _{OL}	Low Level Output Voltage (All Outputs and I/Os Except Port F, Port G, Port H)			TBD	V
	@ V _{DDEXT} = 3.3 V ± 10%, I _{OL} = 2 mA @ V _{DDEXT} = 2.5 V ± 10%, I _{OL} = 2 mA				
V _{OL}	Low Level Output Voltage (Port F7–0)			TBD	V
	@ V _{DDEXT} = 3.3 V ± 10%, I _{OL} = 8 mA @ V _{DDEXT} = 2.5 V ± 10%, I _{OL} = 6 mA				V
V _{OL}	Low Level Output Voltage (Port F15–8, Port G, Port H)			TBD	V
	I _{OL} = 2 mA				
I _{OL}	Low Level Output Current (Maximum Combined for Port F7–0)			TBD	mA
	V _{OL} = 0.5 V max				
I _{IH}	High Level Input Current ¹			TBD	μA
	@ V _{DDEXT} = 3.6 V, V _{IN} = 3.6 V				
I _{IL}	Low Level Input Current ¹			TBD	μA
	@ V _{DDEXT} = 3.6 V, V _{IN} = 0 V				
I _{IHP}	High Level Input Current JTAG ²			TBD	μA
	@ V _{DDEXT} = 3.6 V, V _{IN} = 3.6 V				
I _{OZH}	Three-State Leakage Current ³			TBD	μA
	@ V _{DDEXT} = 3.6 V, V _{IN} = 3.6 V				
I _{OZH5V}	Three-State Leakage Current ⁴			TBD	μA
	@ V _{DDEXT} = 3.0 V, V _{IN} = 5.5 V				
I _{OZL}	Three-State Leakage Current ³			TBD	μA
	@ V _{DDEXT} = 3.6 V, V _{IN} = 0 V				
C _{IN}	Input Capacitance ⁵		TBD	TBD ⁶	pF
	f _{IN} = 1 MHz, T _{AMBIENT} = 25°C, V _{IN} = 2.5 V				
I _{DDHIBERNATE} ⁷	Power Dissipation in Hibernate Mode		50		μA
	@ I _{DD} = nominal				
I _{DDRTC} ⁸	Power Dissipation in Hibernate Mode		tbd		μA
	@ I _{DD} = nominal				

¹ Applies to input signals.

² Applies to JTAG input signals (TCK, TDI, TMS, $\overline{\text{TRST}}$).

³ Applies to three-statable signals.

⁴ Applies to bidirectional signals PJ0 and PJ1.

⁵ Applies to all non-power signals.

⁶ Guaranteed, but not tested.

⁷ Measured at V_{DDEXT} = 3.65 V with voltage regulator off (V_{DDINT} = 0 V).

⁸ Measured at V_{DDRTC} = 3.3 V at 25°C.

ABSOLUTE MAXIMUM RATINGS

Stresses greater than those listed in the table may cause permanent damage to the device. These are stress ratings only. Functional operation of the device at these or any other conditions greater than those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Parameter	Rating
Internal Supply Voltage (V_{DDINT})	tbd V to +tbd V
External (I/O) Supply Voltage (V_{DDEXT})	-0.3 V to +3.8 V
Input Voltage ^{1,2}	-0.5 V to +3.6 V
Input Voltage ^{1,3}	-0.5 V to +5.5 V
Output Voltage Swing	-0.5 V to $V_{DDEXT} + 0.5$ V
Load Capacitance ⁴	200 pF
Storage Temperature Range	-65°C to +150°C
Junction Temperature Underbias	+110°C

¹ Applies to 100% transient duty cycle. For other duty cycles see Table 10.
² Applies only when V_{DDEXT} is within specifications. When V_{DDEXT} is outside specifications, the range is $V_{DDEXT} \pm 0.2$ Volts.
³ Applies to signals SCL, SDA.
⁴ For proper SDRAM controller operation, the maximum load capacitance is 50 pF (at 3.3 V) or 30 pF (at 2.5 V) for ADDR19-1, DATA15-0, ABET-0/SDQM1-0, CLKOUT, SCKE, SA10, SRAS, SCAS, SWE, and SMS.

Table 10. Maximum Duty Cycle for Input Transient Voltage¹

V_{IN} Min (V)	V_{IN} Max (V)	Maximum Duty Cycle
TBD	TBD	100 %
TBD	TBD	40%
TBD	TBD	25%
TBD	TBD	15%
TBD	TBD	10%

¹ Applies to all signal pins/balls with the exception of CLKIN, XTAL, VROUT.

When programming OTP memory on the ADSP-BF512/514/516 processor, the VPPOTP pin/ball must be set to the write value specified in the [Operating Conditions on Page 23](#). There is a finite amount of cumulative time that the write voltage may be applied (dependent on voltage and junction temperature) to VPPOTP over the lifetime of the part. Therefore, maximum OTP memory programming time for the ADSP-BF512/514/516 is shown in [Table 11](#).

tion temperature) to VPPOTP over the lifetime of the part. Therefore, maximum OTP memory programming time for the ADSP-BF512/514/516 is shown in [Table 11](#).

Table 11. Maximum OTP Memory Programming Time for ADSP-BF512/514/516

VPPOTP Voltage (V)	Temperature			
	25°C	85°C	110°C	125°C
6.9	tbd sec	tbd sec	tbd sec	tbd sec
7.0	2400 sec	tbd sec	tbd sec	tbd sec
7.1	1000 sec	tbd sec	tbd sec	tbd sec

PACKAGE INFORMATION

The information presented in [Figure 7](#) and [Table 12](#) provides details about the package branding for the ADSP-BF512/514/516 processor. For a complete listing of product availability, see [Ordering Guide on Page 64](#).

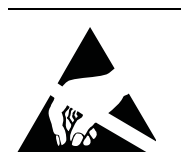


Figure 7. Product Information on Package

Table 12. Package Brand Information

Brand Key	Field Description
ADSP-BF512 or ADSP-BF512F or ADSP-BF514 or ADSP-BF514F or ADSP-BF516 or ADSP-BF516F	Product Name
t	Temperature Range
pp	Package Type
Z	Lead Free Option
ccc	See Ordering Guide
vvvvv.x	Assembly Lot Code
n.n	Silicon Revision
yyww	Date Code

ESD SENSITIVITY



ESD (electrostatic discharge) sensitive device. Charged devices and circuit boards can discharge without detection. Although this product features patented or proprietary circuitry, damage may occur on devices subjected to high energy ESD. Therefore, proper ESD precautions should be taken to avoid performance degradation or loss of functionality.

TIMING SPECIFICATIONS

Table 13 describes the timing requirements for the ADSP-BF512/514/516 processor clocks. Take care in selecting MSEL, SSEL, and CSEL ratios so as not to exceed the maximum core clock and system clock. Table 15 describes phase-locked loop operating conditions.

Table 13. Core Clock (CCLK) Requirements—400 MHz Speed Grade¹

Parameter		Min	Max	Unit
f _{CCLK}	Core Clock Frequency (V _{DDINT} = tbd V minimum)		400	MHz
f _{CCLK}	Core Clock Frequency (V _{DDINT} = tbd V minimum)		TBD	MHz
f _{CCLK}	Core Clock Frequency (V _{DDINT} = tbd V minimum)		TBD	MHz
f _{CCLK}	Core Clock Frequency (V _{DDINT} = tbd V minimum)		TBD	MHz
f _{CCLK}	Core Clock Frequency (V _{DDINT} = tbd V)		TBD	MHz

¹ The speed grade of a given part is printed on the chip's package as shown in Figure 7 on Page 25 and can also be seen on the Ordering Guide on Page 64. It stands for the maximum allowed CCLK frequency at V_{DDINT} = tbd V and the maximum allowed VCO frequency at any supply voltage.

Table 14. Core Clock (CCLK) Requirements—300 MHz Speed Grade¹

Parameter		Min	Max	Unit
f _{CCLK}	Core Clock Frequency (V _{DDINT} = tbd V minimum)		300	MHz
f _{CCLK}	Core Clock Frequency (V _{DDINT} = tbd V minimum)		TBD	MHz
f _{CCLK}	Core Clock Frequency (V _{DDINT} = tbd V minimum)		TBD	MHz
f _{CCLK}	Core Clock Frequency (V _{DDINT} = tbd V minimum)		TBD	MHz
f _{CCLK}	Core Clock Frequency (V _{DDINT} = tbd V)		TBD	MHz

¹ The speed grade of a given part is printed on the chip's package as shown in Figure 7 on Page 25 and can also be seen on the Ordering Guide on Page 64. It stands for the maximum allowed CCLK frequency at V_{DDINT} = tbd V and the maximum allowed VCO frequency at any supply voltage.

Table 15. Phase-Locked Loop Operating Conditions

Parameter		Min	Max	Unit
f _{VCO}	Voltage Controlled Oscillator (VCO) Frequency	50	Speed Grade ¹	MHz

¹ The speed grade of a given part is printed on the chip's package as shown in Figure 7 on Page 25 and can also be seen on the Ordering Guide on Page 64. It stands for the maximum allowed CCLK frequency at V_{DDINT} = tbd V and the maximum allowed VCO frequency at any supply voltage.

Table 16. Maximum SCLK Conditions

Parameter ¹		V _{DDEXT} = 3.3 V, 2.5 V, or 1.8 V		Unit
f _{SCLK}	CLKOUT/SCLK Frequency (V _{DDINT} ≥ tbd V)	80		MHz
f _{SCLK}	CLKOUT/SCLK Frequency (V _{DDINT} < tbd V)	tbd		MHz

¹ t_{SCLK} (= 1/f_{SCLK}) must be greater than or equal to t_{CCLK}.

Clock and Reset Timing

Table 17 and Figure 8 describe clock and reset operations. Per Absolute Maximum Ratings on Page 25, combinations of CLKIN and clock multipliers must not select core/peripheral clocks in excess of 400 MHz/80 MHz.

Table 17. Clock and Reset Timing

Parameter		Min	Max	Unit
<i>Timing Requirements</i>				
t_{CKIN}	CLKIN Period ¹	25.0	100.0	ns
t_{CKINL}	CLKIN Low Pulse ²	10.0		ns
t_{CKINH}	CLKIN High Pulse ²	10.0		ns
$t_{BUFDLAY}$	CLKIN to CLKBUF Delay		10	ns
t_{WRST}	\overline{RESET} Asserted Pulse Width Low ³	11 t_{CKIN}		ns

¹ Combinations of the CLKIN frequency and the PLL clock multiplier must not exceed the allowed f_{VCO} , f_{CLKK} , and f_{SCLK} settings discussed in Table 13 through Table 16.

² Applies to bypass mode and non-bypass mode.

³ Applies after power-up sequence is complete. At power-up, the processor's internal phase-locked loop requires no more than 2000 CLKIN cycles, while \overline{RESET} is asserted, assuming stable power supplies and CLKIN (not including start-up time of external clock oscillator).

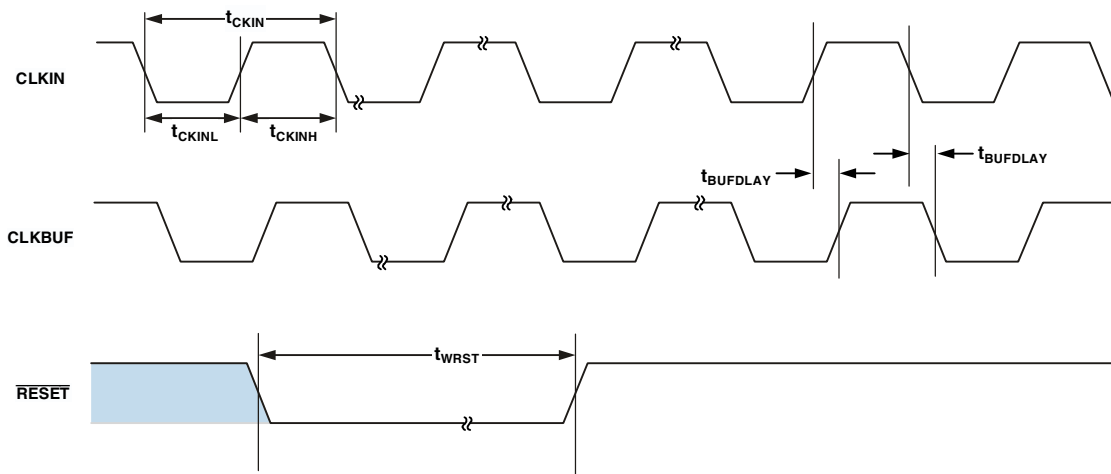


Figure 8. Clock and Reset Timing

Asynchronous Memory Read Cycle Timing

Table 18. Asynchronous Memory Read Cycle Timing

Parameter		Min	Max	Unit
<i>Timing Requirements</i>				
t_{SDAT}	DATA15-0 Setup Before CLKOUT	2.1		ns
t_{HDAT}	DATA15-0 Hold After CLKOUT	0.8		ns
t_{SARDY}	ARDY Setup Before CLKOUT	4.0		ns
t_{HARDY}	ARDY Hold After CLKOUT	0.0		ns
<i>Switching Characteristics</i>				
t_{DO}	Output Delay After CLKOUT ¹		6.0	ns
t_{HO}	Output Hold After CLKOUT ¹	0.8		ns

¹ Output pins/balls include $\overline{AMS3-0}$, $\overline{ABE1-0}$, $\overline{ADDR19-1}$, \overline{AOE} , \overline{ARE} .

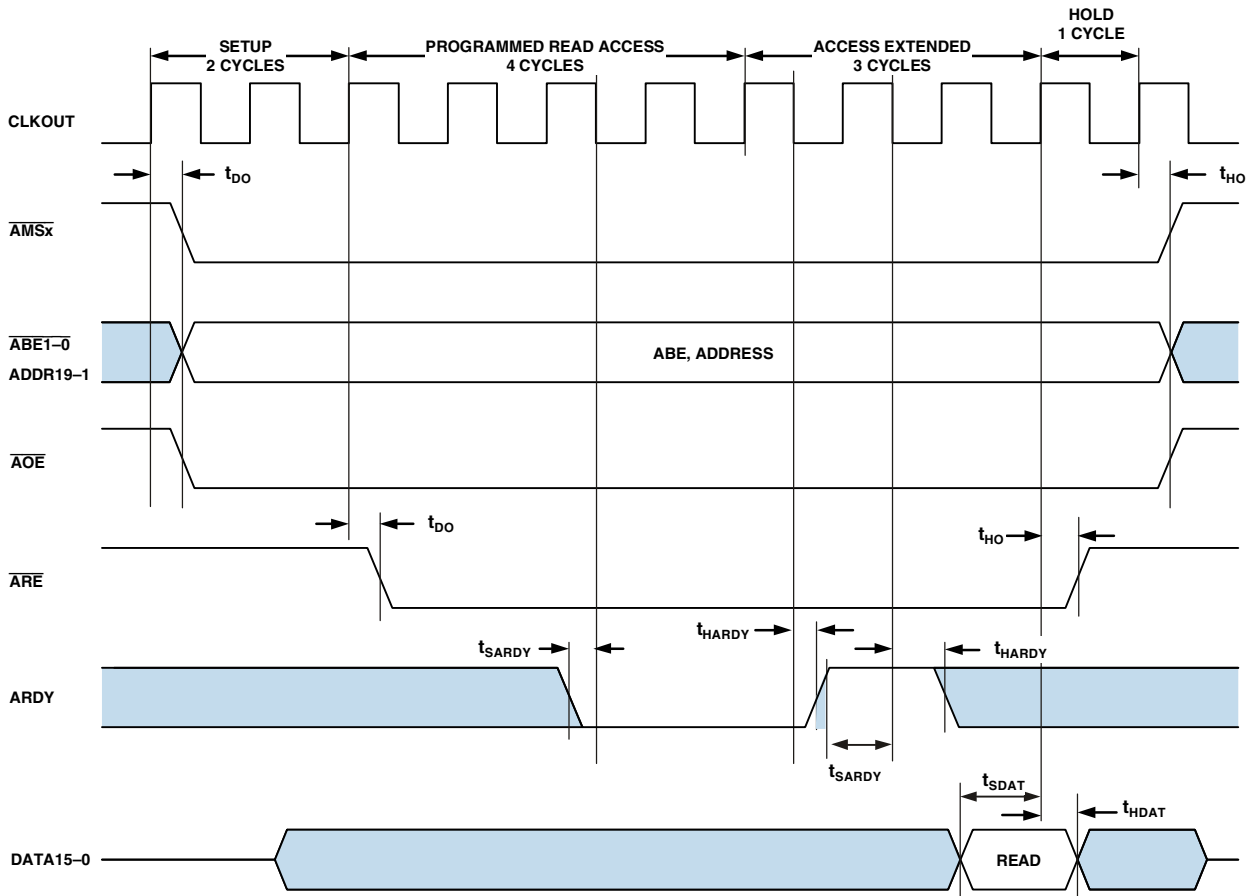


Figure 9. Asynchronous Memory Read Cycle Timing

Asynchronous Memory Write Cycle Timing

Table 19. Asynchronous Memory Write Cycle Timing

Parameter	Min	Max	Unit
<i>Timing Requirements</i>			
t_{SARDY} ARDY Setup Before CLKOUT	4.0		ns
t_{HARDY} ARDY Hold After CLKOUT	0.0		ns
<i>Switching Characteristics</i>			
t_{DDAT} DATA15-0 Disable After CLKOUT		6.0	ns
t_{ENDAT} DATA15-0 Enable After CLKOUT	1.0		ns
t_{DO} Output Delay After CLKOUT ¹		6.0	ns
t_{HO} Output Hold After CLKOUT ¹	0.8		ns

¹ Output pins/balls include $\overline{AMS3-0}$, $\overline{ABE1-0}$, $\overline{ADDR19-1}$, $\overline{DATA15-0}$, \overline{AOE} , \overline{AWE} .

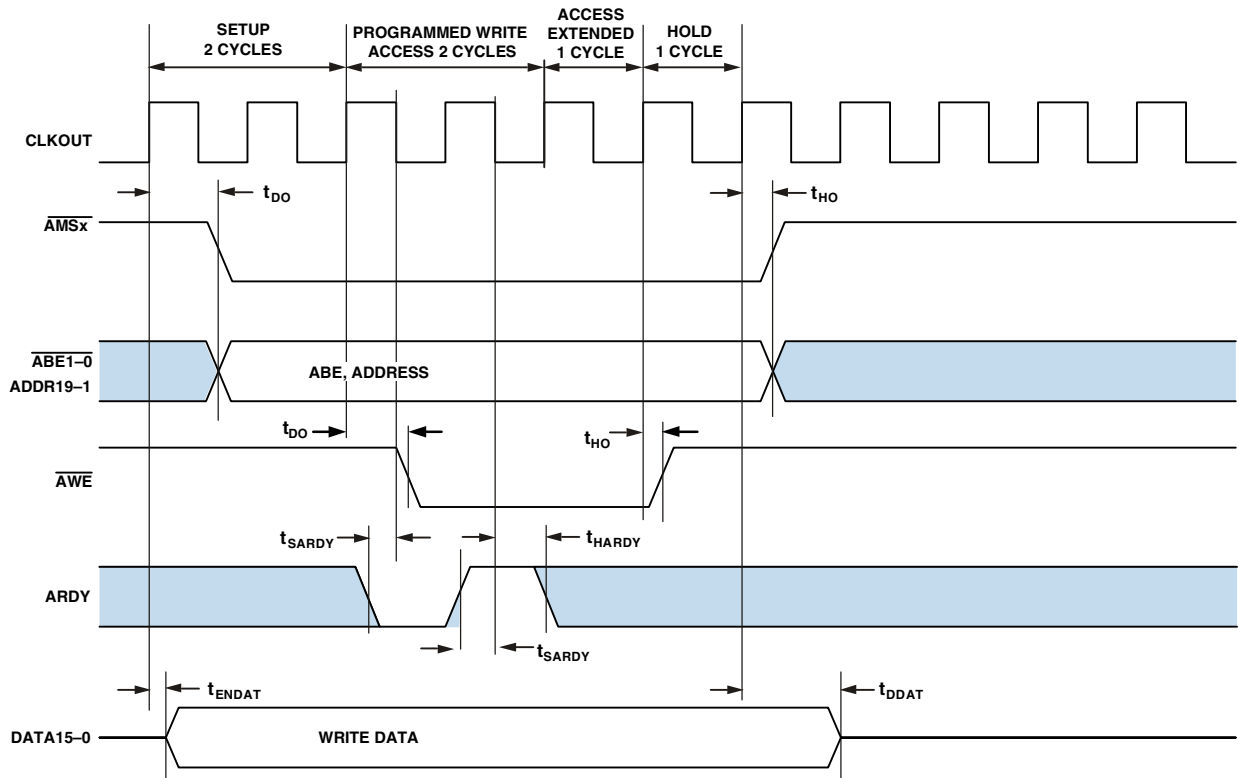


Figure 10. Asynchronous Memory Write Cycle Timing

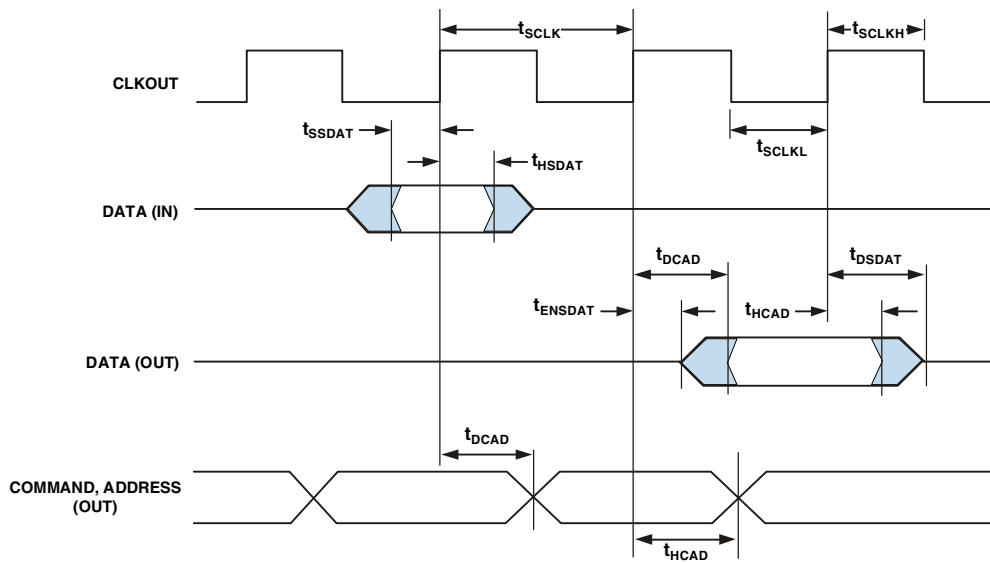
SDRAM Interface Timing

Table 20. SDRAM Interface Timing (VDD_{INT} = 1.2 V)

Parameter		Min	Max	Unit
<i>Timing Requirements</i>				
t _{SSDAT}	Data Setup Before CLKOUT	1.5		ns
t _{HSDAT}	Data Hold After CLKOUT	0.8		ns
<i>Switching Characteristics</i>				
t _{SCLK}	CLKOUT Period ¹	12.5		ns
t _{SCLKH}	CLKOUT Width High	2.5		ns
t _{SCLKL}	CLKOUT Width Low	2.5		ns
t _{DCAD}	Command, Address, Data Delay After CLKOUT ²		4.4	ns
t _{HCAD}	Command, Address, Data Hold After CLKOUT ²	1.0		ns
t _{DSDAT}	Data Disable After CLKOUT		4.4	ns
t _{ENSDAT}	Data Enable After CLKOUT	1.0		ns

¹ The t_{SCLK} value is the inverse of the f_{SCLK} specification discussed in Table 16. Package type and reduced supply voltages affect the best-case value of 7.5 ns listed here.

² Command pins/balls include: $\overline{\text{SRAS}}$, $\overline{\text{SCAS}}$, $\overline{\text{SWE}}$, $\overline{\text{SDQM}}$, $\overline{\text{SMS}}$, SA10, SCKE.



NOTE: COMMAND = $\overline{\text{SRAS}}$, $\overline{\text{SCAS}}$, $\overline{\text{SWE}}$, $\overline{\text{SDQM}}$, $\overline{\text{SMS}}$, SA10, SCKE.

Figure 11. SDRAM Interface Timing

External DMA Request Timing

Table 21 and Figure 12 describe the External DMA Request operations.

Table 21. External DMA Request Timing

Parameter		Min	Max	Unit
<i>Timing Parameters</i>				
t_{DR}	DMARx Asserted to CLKOUT High Setup	6.0		ns
t_{DH}	CLKOUT High to DMARx Deasserted Hold Time	0.0		ns
$t_{DMARACT}$	DMARx Active Pulse Width	$1.0 \times t_{SCLK}$		ns
$t_{DMARINACT}$	DMARx Inactive Pulse Width	$1.75 \times t_{SCLK}$		ns

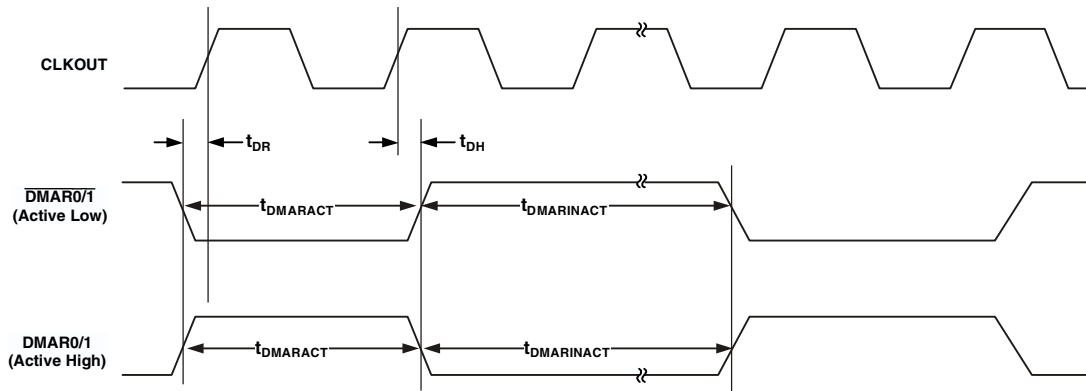


Figure 12. External DMA Request Timing

Parallel Peripheral Interface Timing

Table 22 and Figure 13 on Page 32, Figure 17 on Page 36, and Figure 18 on Page 37 describe parallel peripheral interface operations.

Table 22. Parallel Peripheral Interface Timing

Parameter	Min	Max	Unit
<i>Timing Requirements</i>			
t_{PCLKW}	PPI_CLK Width ¹		6.4 ns
t_{PCLK}	PPI_CLK Period ¹		16.0 ns
<i>Timing Requirements - GP Input and Frame Capture Modes</i>			
t_{SFSPE}	External Frame Sync Setup Before PPI_CLK (Nonsampling Edge for Rx, Sampling Edge for Tx)		6.7 ns
t_{HFSPE}	External Frame Sync Hold After PPI_CLK		1.0 ns
t_{SDRPE}	Receive Data Setup Before PPI_CLK		3.5 ns
t_{HDRPE}	Receive Data Hold After PPI_CLK		1.5 ns
<i>Switching Characteristics - GP Output and Frame Capture Modes</i>			
t_{DFSPE}	Internal Frame Sync Delay After PPI_CLK		8.8 ns
$t_{HOFSPPE}$	Internal Frame Sync Hold After PPI_CLK		1.7 ns
t_{DDTPE}	Transmit Data Delay After PPI_CLK		8.8 ns
t_{HDTPE}	Transmit Data Hold After PPI_CLK		1.8 ns

¹ PPI_CLK frequency cannot exceed $f_{SCLK}/2$

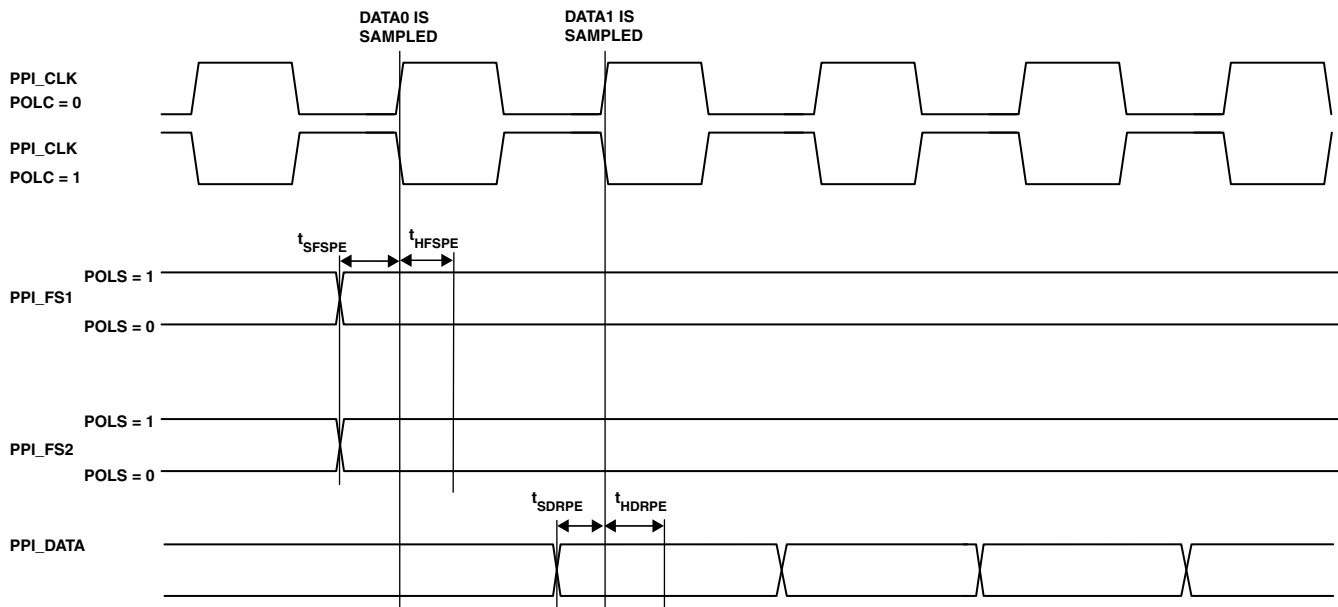


Figure 13. PPI GP Rx Mode with External Frame Sync Timing

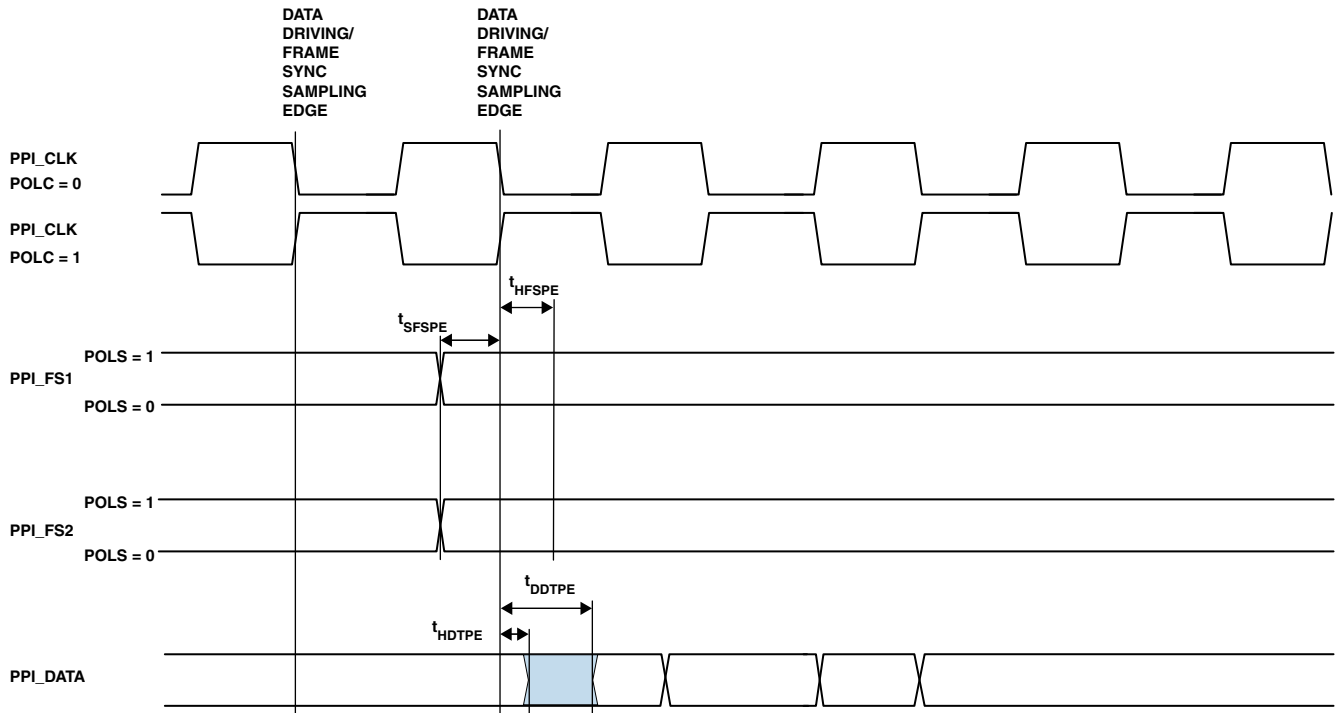


Figure 14. PPI GP Tx Mode with External Frame Sync Timing

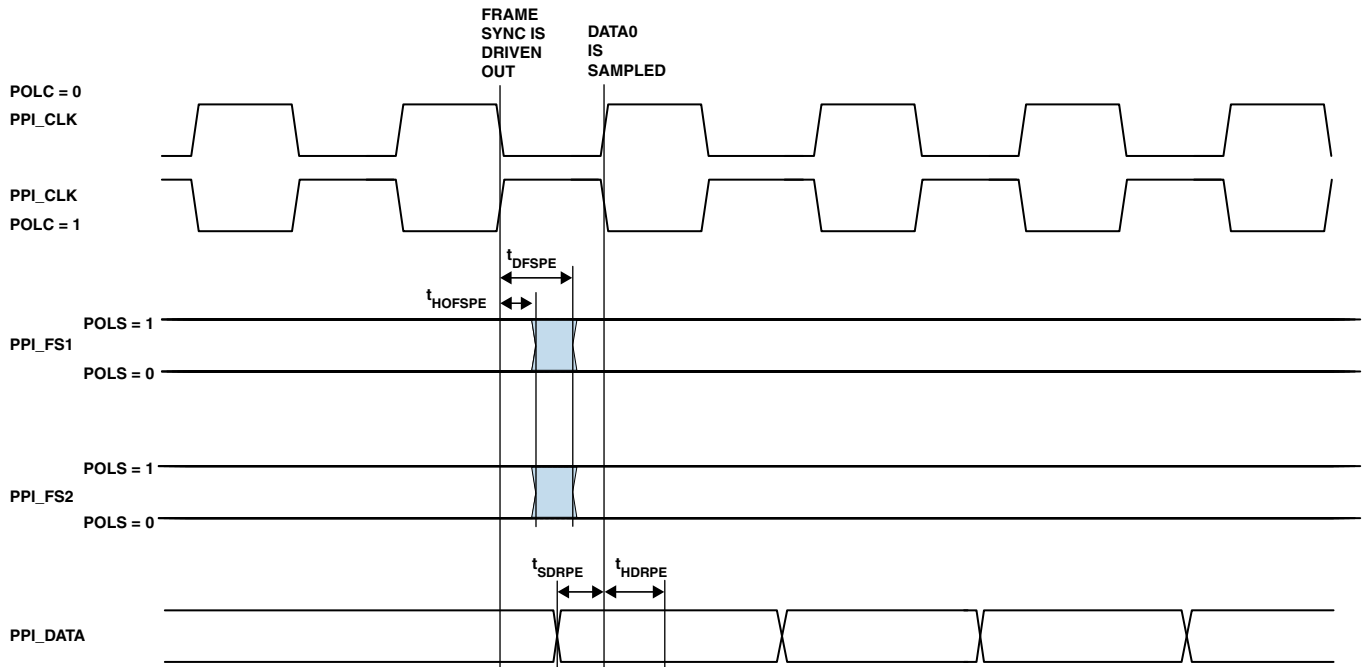


Figure 15. PPI GP Rx Mode with Internal Frame Sync Timing

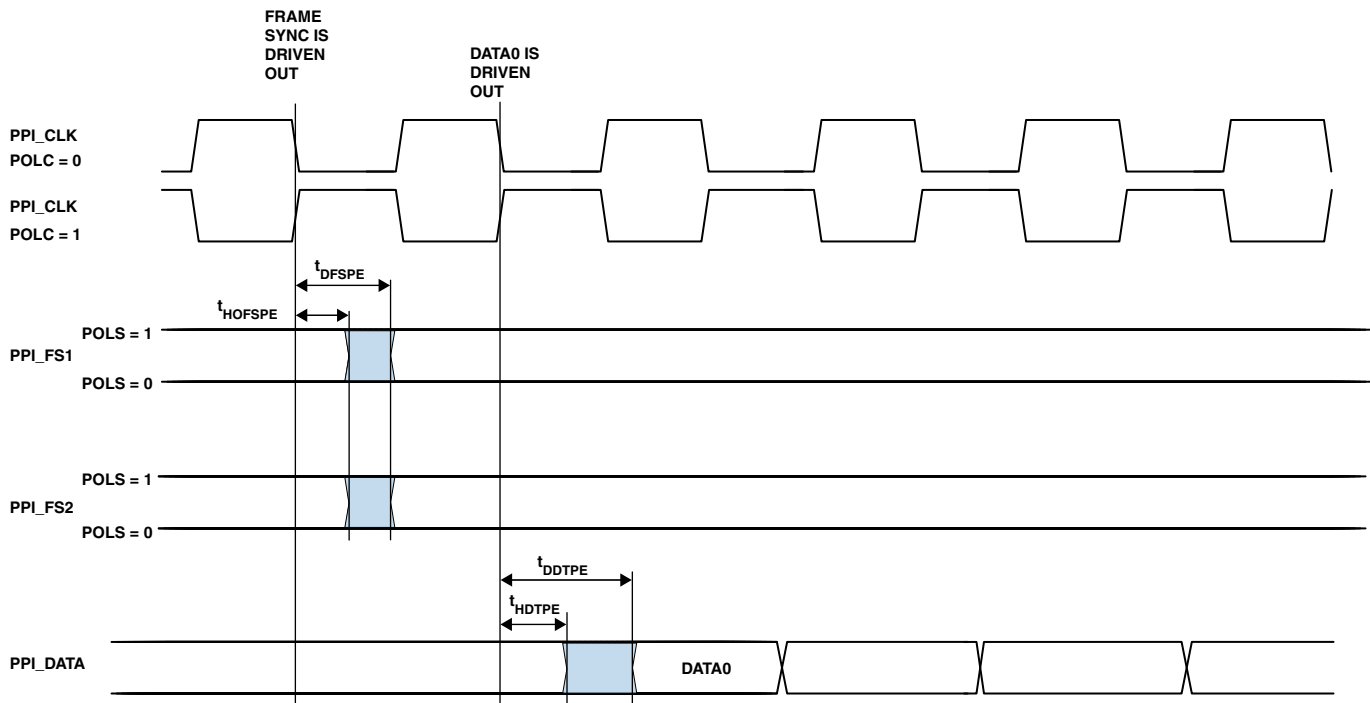


Figure 16. PPI GP Tx Mode with Internal Frame Sync Timing

Serial Ports

Table 23 through Table 26 on Page 36 and Figure 17 on Page 36 through Figure 18 on Page 37 describe serial port operations.

Table 23. Serial Ports—External Clock

Parameter	Min	Max	Unit
<i>Timing Requirements</i>			
t _{SFSE}	TFSx/RFSx Setup Before TSCLKx/RSCLKx ¹		3.0 ns
t _{HFSE}	TFSx/RFSx Hold After TSCLKx/RSCLKx ¹		3.0 ns
t _{SDRE}	Receive Data Setup Before RSCLKx ¹		3.0 ns
t _{HDRE}	Receive Data Hold After RSCLKx ¹		3.6 ns
t _{SCLKEW}	TSCLKx/RSCLKx Width		5.4 ns
t _{SCLKE}	TSCLKx/RSCLKx Period		8.0 ns
<i>Switching Characteristics</i>			
t _{DFSE}	TFSx/RFSx Delay After TSCLKx/RSCLKx (Internally Generated TFSx/RFSx) ²		12.0 ns
t _{HOFSE}	TFSx/RFSx Hold After TSCLKx/RSCLKx (Internally Generated TFSx/RFSx) ¹		0.0 ns
t _{DDTE}	Transmit Data Delay After TSCLKx ¹		12.0 ns
t _{HDTTE}	Transmit Data Hold After TSCLKx ¹		0.0 ns

¹ Referenced to sample edge.

² Referenced to drive edge.

Table 24. Serial Ports—Internal Clock

Parameter	Min	Max	Unit
<i>Timing Requirements</i>			
t _{SFSI}	TFSx/RFSx Setup Before TSCLKx/RSCLKx ¹		11.3 ns
t _{HFSI}	TFSx/RFSx Hold After TSCLKx/RSCLKx ¹		-1.5 ns
t _{SDRI}	Receive Data Setup Before RSCLKx ¹		11.3 ns
t _{HDRI}	Receive Data Hold After RSCLKx ¹		-1.5 ns
t _{SCLKEW}	TSCLKx/RSCLKx Width		5.4 ns
t _{SCLKE}	TSCLKx/RSCLKx Period		18.0 ns
<i>Switching Characteristics</i>			
t _{DFSI}	TFSx/RFSx Delay After TSCLKx/RSCLKx (Internally Generated TFSx/RFSx) ²		3.0 ns
t _{HOFSI}	TFSx/RFSx Hold After TSCLKx/RSCLKx (Internally Generated TFSx/RFSx) ¹		-4.0 ns
t _{DDTI}	Transmit Data Delay After TSCLKx ¹		3.0 ns
t _{HDTI}	Transmit Data Hold After TSCLKx ¹		-1.8 ns
t _{SCLKIW}	TSCLKx/RSCLKx Width		5.4 ns

¹ Referenced to sample edge.

² Referenced to drive edge.

Table 25. Serial Ports—Enable and Three-State

Parameter	Min	Max	Unit
<i>Switching Characteristics</i>			
t _{DTENE}	Data Enable Delay from External TSCLKx ¹		0.0 ns
t _{DDTTE}	Data Disable Delay from External TSCLKx ¹		10.0 ns
t _{DTENI}	Data Enable Delay from Internal TSCLKx ¹		-2.0 ns
t _{DDTTI}	Data Disable Delay from Internal TSCLKx ¹		3.0 ns

¹ Referenced to drive edge.

Table 26. External Late Frame Sync

Parameter	Min	Max	Unit
<i>Switching Characteristics</i>			
$t_{DDTLFSE}$		10.0	ns
$t_{DTENLFSE}$	0.0		ns

¹ MCE = 1, TFSx enable and TFSx valid follow $t_{DDTENFS}$ and $t_{DDTLFSE}$.

² If external RFSx/TFSx setup to RSCLKx/TSCLKx > $t_{SCLKE}/2$ then $t_{DDTTE/I}$ and $t_{DTENE/I}$ apply, otherwise $t_{DDTLFSE}$ and $t_{DTENLFSE}$ apply.

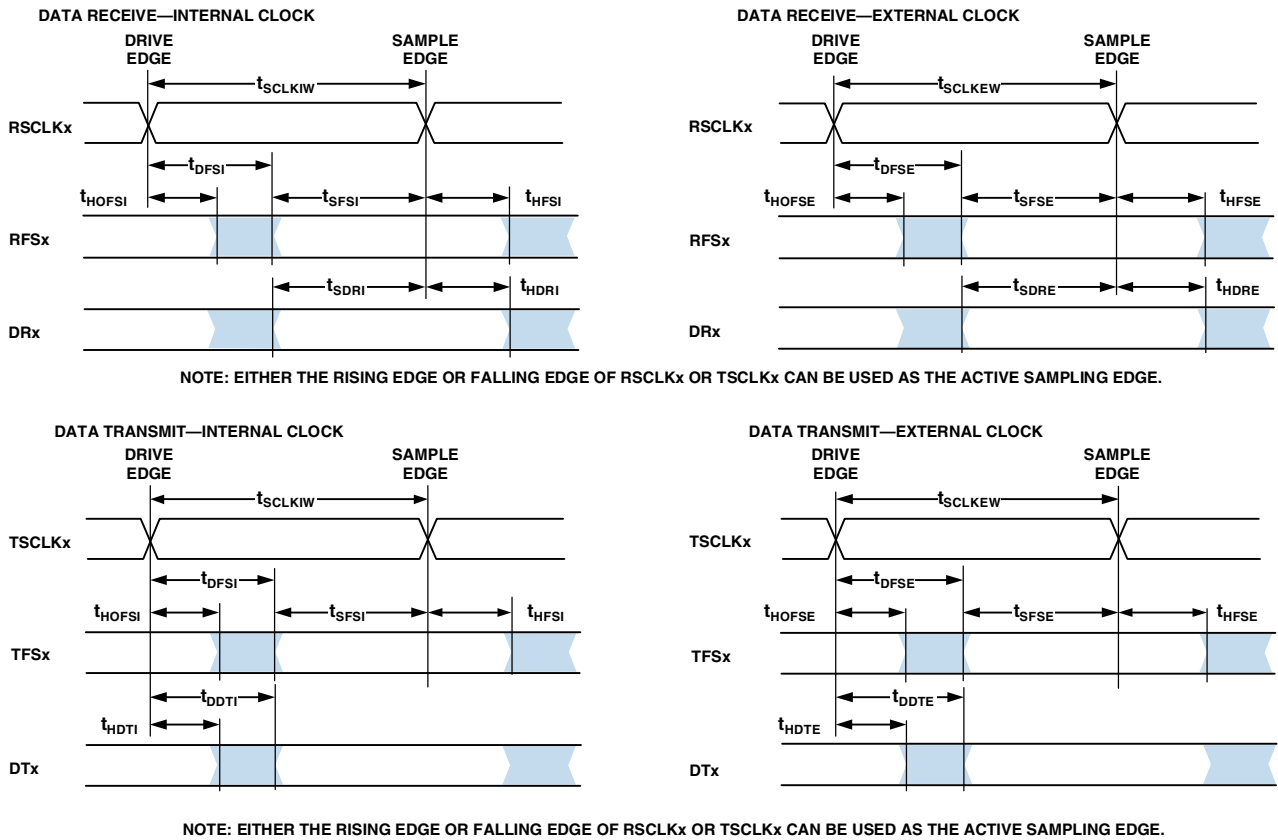
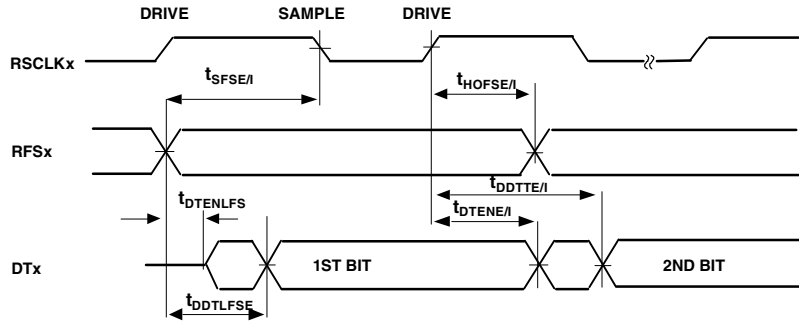


Figure 17. Serial Ports

EXTERNAL RFSx WITH MCE = 1, MFD = 0



LATE EXTERNAL TFSx

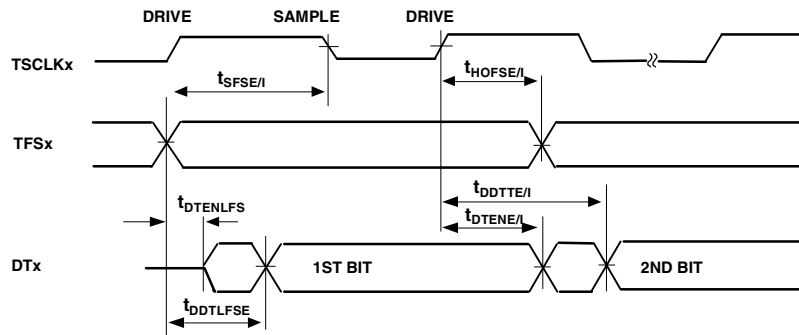


Figure 18. External Late Frame Sync

Serial Peripheral Interface (SPI) Port—Master Timing

Table 27 and Figure 19 describe SPI port master operations.

Table 27. Serial Peripheral Interface (SPI) Port—Master Timing

Parameter		Min	Max	Unit
<i>Timing Requirements</i>				
t_{SSPIDM}	Data Input Valid to SCK Edge (Data Input Setup)	11.6		ns
t_{HSPIDM}	SCK Sampling Edge to Data Input Invalid	-1.5		ns
<i>Switching Characteristics</i>				
t_{SDSCIM}	$\overline{\text{SPISSELx}}$ low to First SCK Edge	$2 \times t_{SCLK} - 1.5$		ns
t_{SPICHM}	Serial Clock High Period	$2 \times t_{SCLK} - 1.5$		ns
t_{SPICLM}	Serial Clock Low Period	$2 \times t_{SCLK} - 1.5$		ns
t_{SPICLK}	Serial Clock Period	$4 \times t_{SCLK} - 1.5$		ns
t_{HDSM}	Last SCK Edge to $\overline{\text{SPISSELx}}$ High	$2 \times t_{SCLK} - 1.5$		ns
t_{SPITDM}	Sequential Transfer Delay	$2 \times t_{SCLK} - 1.5$		ns
$t_{DDSPIDM}$	SCK Edge to Data Out Valid (Data Out Delay)	0	6	ns
$t_{HDSPIDM}$	SCK Edge to Data Out Invalid (Data Out Hold)	-1.0	4.0	ns

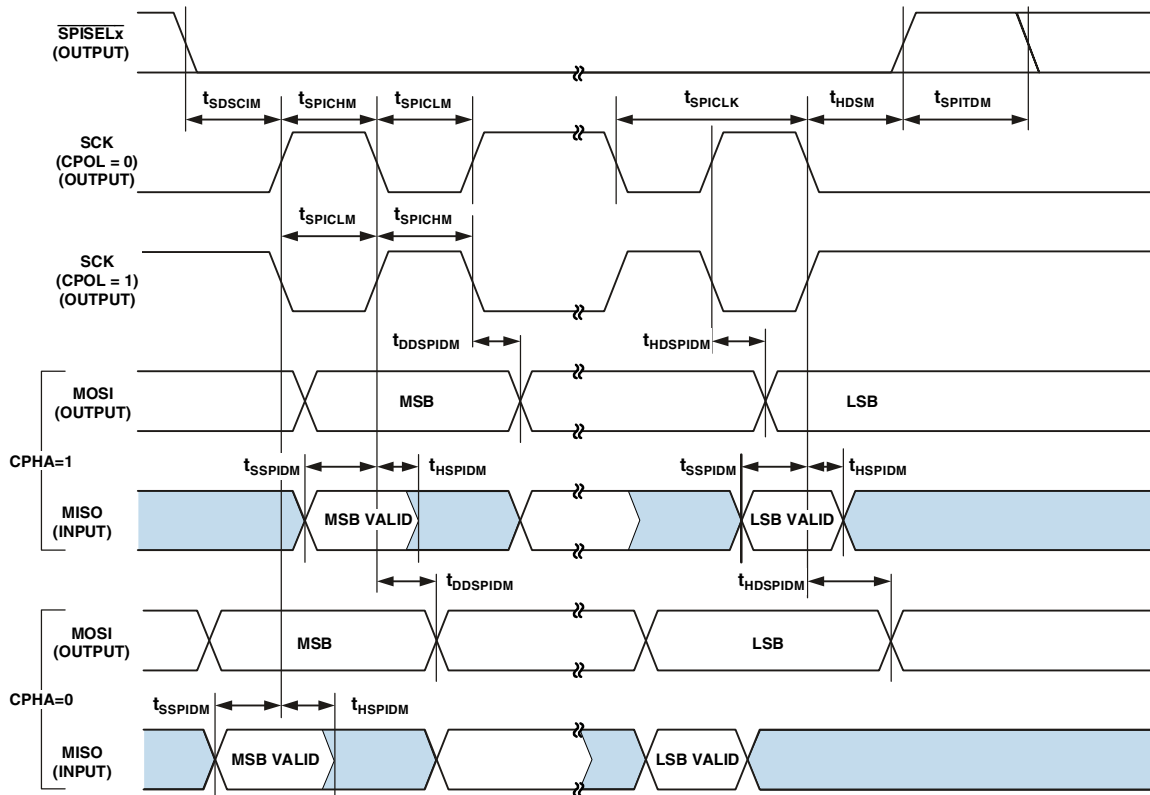


Figure 19. Serial Peripheral Interface (SPI) Port—Master Timing

Serial Peripheral Interface (SPI) Port—Slave Timing

Table 28 and Figure 20 describe SPI port slave operations.

Table 28. Serial Peripheral Interface (SPI) Port—Slave Timing

Parameter		Min	Max	Unit
<i>Timing Requirements</i>				
t_{SPICHS}	Serial Clock High Period	$2 \times t_{SCLK} - 1.5$		ns
t_{SPICLS}	Serial Clock Low Period	$2 \times t_{SCLK} - 1.5$		ns
t_{SPICLK}	Serial Clock Period	$4 \times t_{SCLK} - 1.5$		ns
t_{HDS}	Last SCK Edge to \overline{SPISS} Not Asserted	$2 \times t_{SCLK} - 1.5$		ns
t_{SPITDS}	Sequential Transfer Delay	$2 \times t_{SCLK} - 1.5$		ns
t_{SDSCI}	\overline{SPISS} Assertion to First SCK Edge	$2 \times t_{SCLK} - 1.5$		ns
t_{SSPID}	Data Input Valid to SCK Edge (Data Input Setup)	1.6		ns
t_{HSPID}	SCK Sampling Edge to Data Input Invalid	1.6		ns
<i>Switching Characteristics</i>				
t_{DSOE}	\overline{SPISS} Assertion to Data Out Active	0	8.5	ns
t_{DSDHI}	\overline{SPISS} Deassertion to Data High Impedance	0	8.5	ns
t_{DDSPID}	SCK Edge to Data Out Valid (Data Out Delay)	0	10	ns
t_{HDSPID}	SCK Edge to Data Out Invalid (Data Out Hold)	0	10	ns

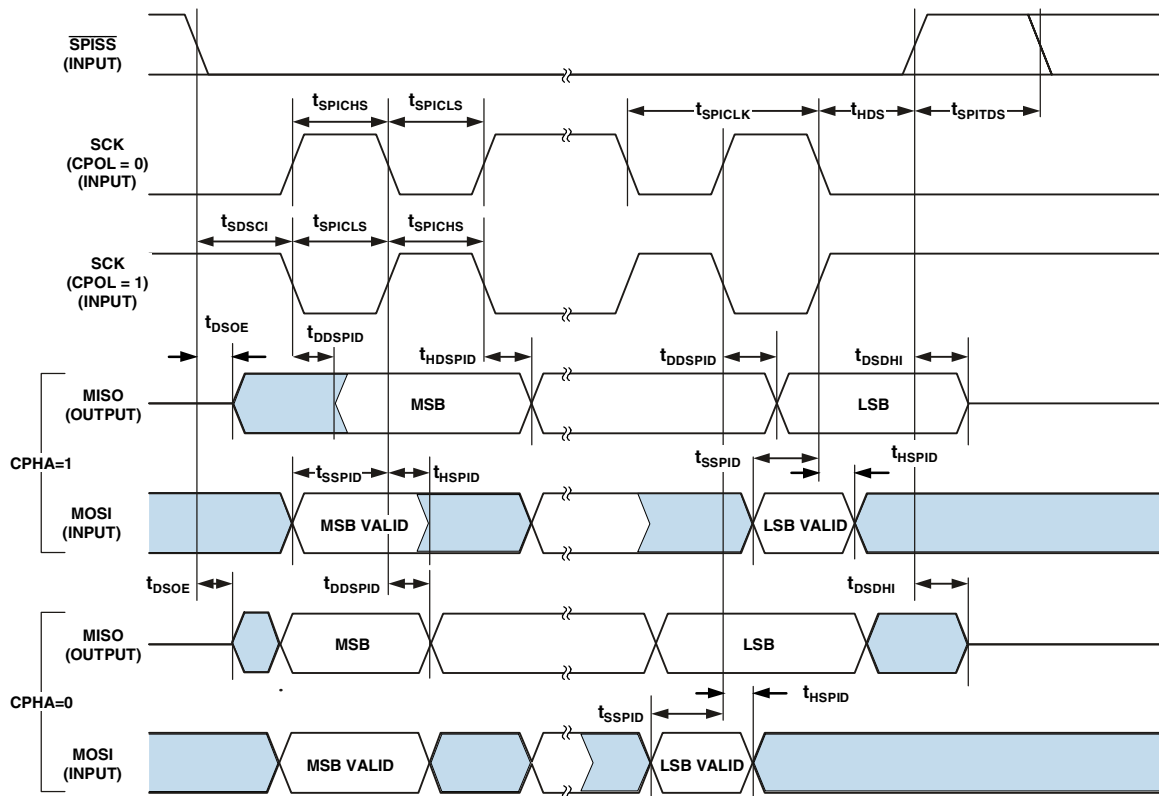


Figure 20. Serial Peripheral Interface (SPI) Port—Slave Timing

General-Purpose Port Timing

Table 29 and Figure 21 describe general-purpose port operations.

Table 29. General-Purpose Port Timing

Parameter		Min	Max	Unit
<i>Timing Requirement</i>				
t_{WFI}	General-Purpose Port Signal Input Pulse Width	$t_{SCLK} + 1$		ns
<i>Switching Characteristics</i>				
t_{GPOD}	General-Purpose Port Signal Output Delay from CLKOUT Low	0	9.66	ns

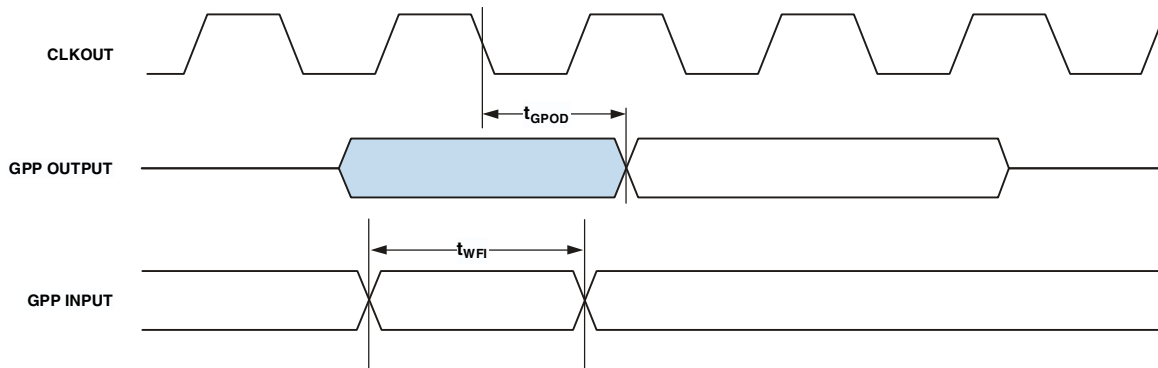


Figure 21. General-Purpose Port Timing

Timer Cycle Timing

Table 30 and Figure 22 describe timer expired operations. The input signal is asynchronous in “width capture mode” and “external clock mode” and has an absolute maximum input frequency of ($f_{SCLK}/2$) MHz.

Table 30. Timer Cycle Timing

Parameter	Min	Max	Unit
<i>Timing Characteristics</i>			
t_{WL} Timer Pulse Width Input Low (Measured In SCLK Cycles) ¹	$1 \times t_{SCLK}$		ns
t_{WH} Timer Pulse Width Input High (Measured In SCLK Cycles) ¹	$1 \times t_{SCLK}$		ns
t_{TIS} Timer Input Setup Time Before CLKOUT Low ²	5		ns
t_{TIH} Timer Input Hold Time After CLKOUT Low ²	-2		ns
<i>Switching Characteristics</i>			
t_{HTO} Timer Pulse Width Output (Measured In SCLK Cycles)	$1 \times t_{SCLK}$	$(2^{32}-1)t_{SCLK}$	ns
t_{TOD} Timer Output Update Delay After CLKOUT High		8.1	ns

¹ The minimum pulse widths apply for TMRx signals in width capture and external clock modes. They also apply to the PF15 or PPI_CLK signals in PWM output mode.
² Either a valid setup and hold time or a valid pulse width is sufficient. There is no need to resynchronize programmable flag inputs.

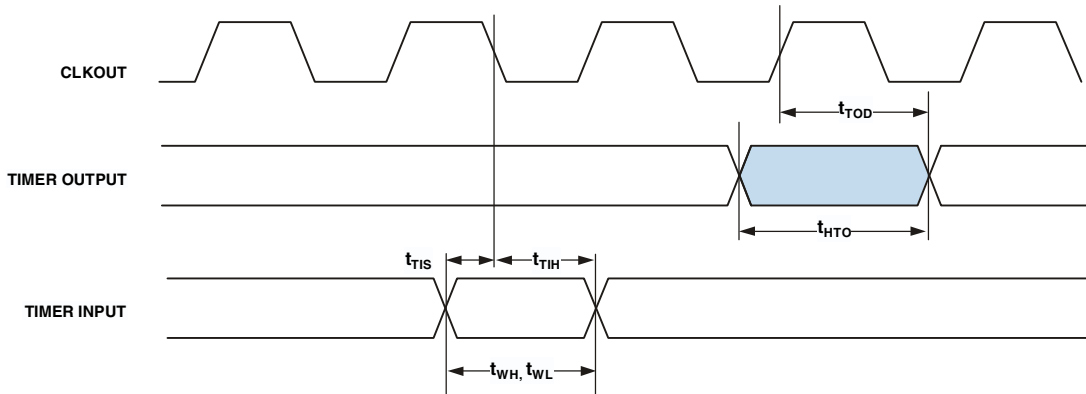


Figure 22. Timer Cycle Timing

Timer Clock Timing

Table 31 and Figure 23 describe timer clock timing.

Table 31. Timer Clock Timing

Parameter	Min	Max	Unit
<i>Switching Characteristic</i>			
t_{TODP} Timer Output Update Delay After PPICLK High		12.64	ns

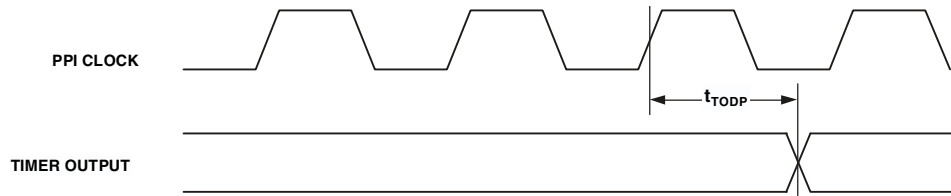


Figure 23. Timer Clock Timing

OTP Timing

Table 32. OTP Timing Parameters¹

Parameter		Min	Max	Units
t_{FACC}	OTP Memory Bit Read Access Time	tbd		ns
t_{RPGM}	OTP Memory Charge Pump Release Time	tbd		ms
t_{CPS}	OTP Memory Charge Pump Setup Time		tbd	ms
t_{CPH}	OTP Memory Charge Pump Hold Time		tbd	ms
t_{PGM}	OTP Memory Bit Program Time	tbd		ms

¹These parameters are programmed into the OTP_TIMING register. See ADSP-BF512/514/516 Blackfin Processor Hardware Reference and the application note "EE-TBD: Programming OTP on Blackfin Processors" for details.

JTAG Test And Emulation Port Timing

Table 33 and Figure 24 describe JTAG port operations.

Table 33. JTAG Port Timing

Parameter		Min	Max	Unit
<i>Timing Parameters</i>				
t_{TCK}	TCK Period	20		ns
t_{STAP}	TDI, TMS Setup Before TCK High	4		ns
t_{HTAP}	TDI, TMS Hold After TCK High	4		ns
t_{SSYS}	System Inputs Setup Before TCK High ¹	4		ns
t_{HSYS}	System Inputs Hold After TCK High ¹	5		ns
t_{TRSTW}	\overline{TRST} Pulse Width ² (measured in TCK cycles)	4		TCK
<i>Switching Characteristics</i>				
t_{DTDO}	TDO Delay from TCK Low		10	ns
t_{DSYS}	System Outputs Delay After TCK Low ³	0	12	ns

¹ System Inputs = DATA15-0, SCL, SDA, TFS0, TSCLK0, RSCLK0, RFS0, DR0PRI, DR0SEC, PF15-0, PG15-0, PH7-0, MDIO, TCK, TD1, TMS, \overline{TRST} , \overline{RESET} , \overline{NMI} , BMODE2-0.

² 50 MHz Maximum

³ System Outputs = DATA15-0, ADDR19-1, ABE1-0, ARE, AWE, AMS1-0, SRAS, SCAS, SWE, SCKE, CLKOUT, SA10, SMS, SCL, SDA, TSCLK0, TFS0, RFS0, RSCLK0, DT0PRI, DT0SEC, PF15-0, PG15-0, PH7-0, MDC, MDIO, TD0, EMU.

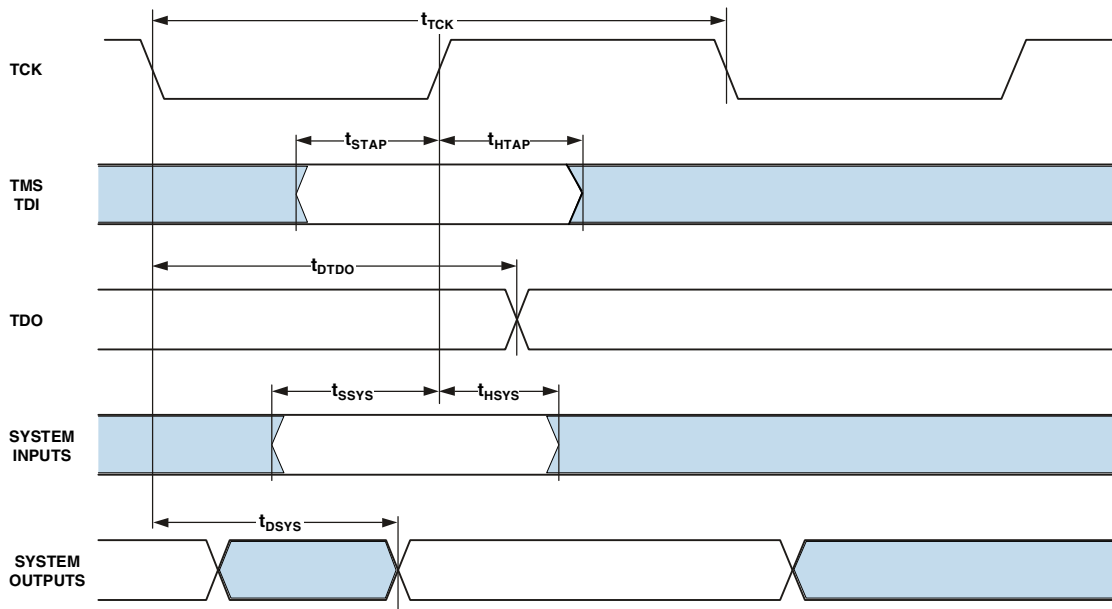


Figure 24. JTAG Port Timing

10/100 Ethernet MAC Controller Timing

Table 34 through Table 39 and Figure 25 through Figure 30 describe the 10/100 ethernet MAC Controller operations.

Table 34. 10/100 Ethernet MAC Controller Timing: MII Receive Signal

Parameter ¹		Min	Max	Unit
t _{ERXCLKF}	ERxCLK Frequency (f _{SCLK} = SCLK Frequency)	None	25 MHz + 1% f _{SCLK} + 1%	ns
t _{ERXCLKW}	ERxCLK Width (t _{ERXCLK} = ERxCLK Period)	t _{ERXCLK} × 35%	t _{ERXCLK} × 65%	ns
t _{ERXCLKIS}	Rx Input Valid to ERxCLK Rising Edge (Data In Setup)	7.5		ns
t _{ERXCLKIH}	ERxCLK Rising Edge to Rx Input Invalid (Data In Hold)	7.5		ns

¹ MII inputs synchronous to ERxCLK are ERxD3–0, ERxDV, and ERxER.

Table 35. 10/100 Ethernet MAC Controller Timing: MII Transmit Signal

Parameter ¹		Min	Max	Unit
t _{ETF}	ETxCLK Frequency (f _{SCLK} = SCLK Frequency)	None	25 MHz + 1% f _{SCLK} + 1%	ns
t _{ETXCLKW}	ETxCLK Width (t _{ETXCLK} = ETxCLK Period)	t _{ETXCLK} × 35%	t _{ETXCLK} × 65%	ns
t _{ETXCLKOV}	ETxCLK Rising Edge to Tx Output Valid (Data Out Valid)		20	ns
t _{ETXCLKOH}	ETxCLK Rising Edge to Tx Output Invalid (Data Out Hold)	0		ns

¹ MII outputs synchronous to ETxCLK are ETxD3–0.

Table 36. 10/100 Ethernet MAC Controller Timing: RMII Receive Signal

Parameter ¹		Min	Max	Unit
t _{EREFCLKF}	REF_CLK Frequency (f _{SCLK} = SCLK Frequency)	None	50 MHz + 1% 2 × f _{SCLK} + 1%	ns
t _{EREFCLKW}	REF_CLK Width (t _{EREFCLK} = EREFCLK Period)	t _{EREFCLK} × 35%	t _{EREFCLK} × 65%	ns
t _{EREFCLKIS}	Rx Input Valid to RMII REF_CLK Rising Edge (Data In Setup)	4		ns
t _{EREFCLKIH}	RMII REF_CLK Rising Edge to Rx Input Invalid (Data In Hold)	2		ns

¹ RMII inputs synchronous to RMII REF_CLK are ERxD1–0, RMII CRS_DV, and ERxER.

Table 37. 10/100 Ethernet MAC Controller Timing: RMII Transmit Signal

Parameter ¹		Min	Max	Unit
t _{EREFCLKOV}	RMII REF_CLK Rising Edge to Tx Output Valid (Data Out Valid)		8.1	ns
t _{EREFCLKOH}	RMII REF_CLK Rising Edge to Tx Output Invalid (Data Out Hold)	2		ns

¹ RMII outputs synchronous to RMII REF_CLK are ETxD1–0.

Table 38. 10/100 Ethernet MAC Controller Timing: MII/RMII Asynchronous Signal

Parameter ^{1,2}		Min	Max	Unit
t_{ECOLH}	COL Pulse Width High	$t_{ETxCLK} \times 1.5$		ns
t_{ECOLL}	COL Pulse Width Low	$t_{ERxCLK} \times 1.5$		ns
t_{ECSRSH}	CRS Pulse Width High	$t_{ETxCLK} \times 1.5$		ns
t_{ECRSL}	CRS Pulse Width Low	$t_{ETxCLK} \times 1.5$		ns

¹ MII/RMII asynchronous signals are COL, CRS. These signals are applicable in both MII and RMII modes. The asynchronous COL input is synchronized separately to both the ETxCLK and the ERxCLK, and must have a minimum pulse width high or low at least 1.5 times the period of the slower of the two clocks.

² The asynchronous CRS input is synchronized to the ETxCLK, and must have a minimum pulse width high or low at least 1.5 times the period of ETxCLK.

Table 39. 10/100 Ethernet MAC Controller Timing: MII Station Management

Parameter ¹		Min	Max	Unit
t_{MDIOS}	MDIO Input Valid to MDC Rising Edge (Setup)	11.5		ns
t_{MDCIH}	MDC Rising Edge to MDIO Input Invalid (Hold)	11.5		ns
t_{MDCOV}	MDC Falling Edge to MDIO Output Valid	25		ns
t_{MDCOH}	MDC Falling Edge to MDIO Output Invalid (Hold)	-1		ns

¹ MDC/MDIO is a 2-wire serial bidirectional port for controlling one or more external PHYs. MDC is an output clock whose minimum period is programmable as a multiple of the system clock SCLK. MDIO is a bidirectional data line.

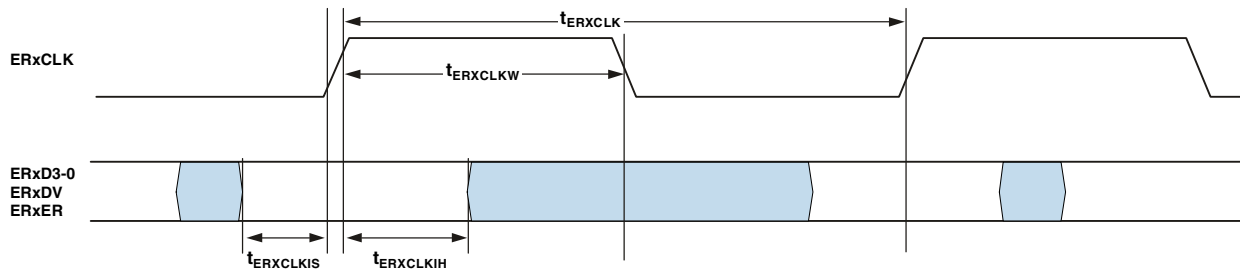


Figure 25. 10/100 Ethernet MAC Controller Timing: MII Receive Signal

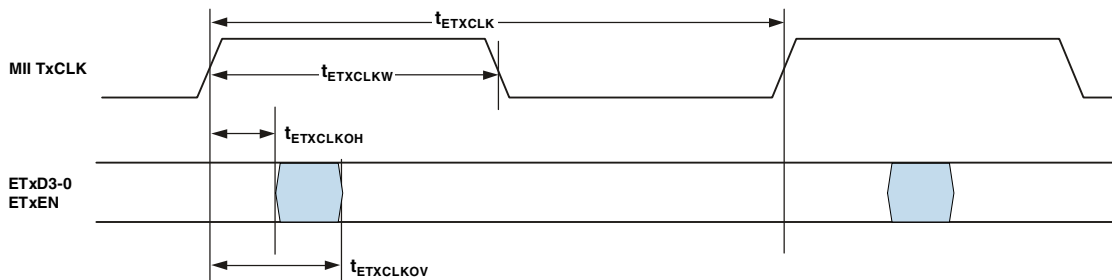


Figure 26. 10/100 Ethernet MAC Controller Timing: MII Transmit Signal

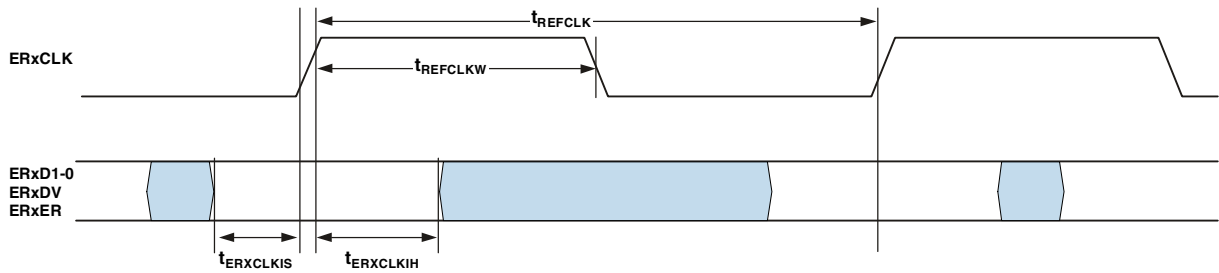


Figure 27. 10/100 Ethernet MAC Controller Timing: RMI Receive Signal

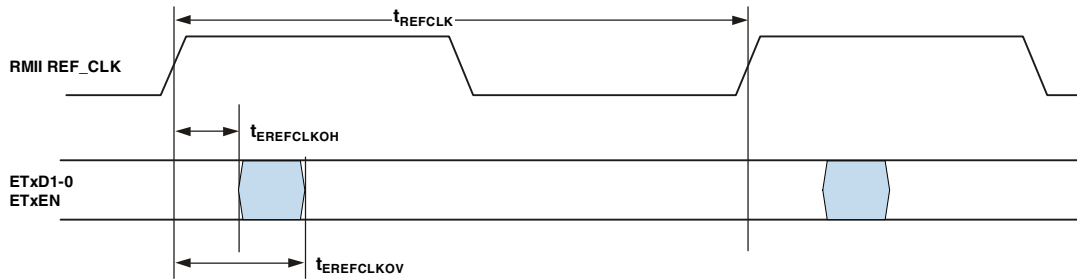


Figure 28. 10/100 Ethernet MAC Controller Timing: RMI Transmit Signal

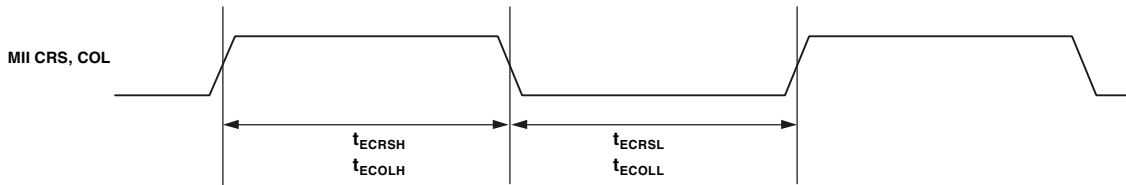


Figure 29. 10/100 Ethernet MAC Controller Timing: Asynchronous Signal

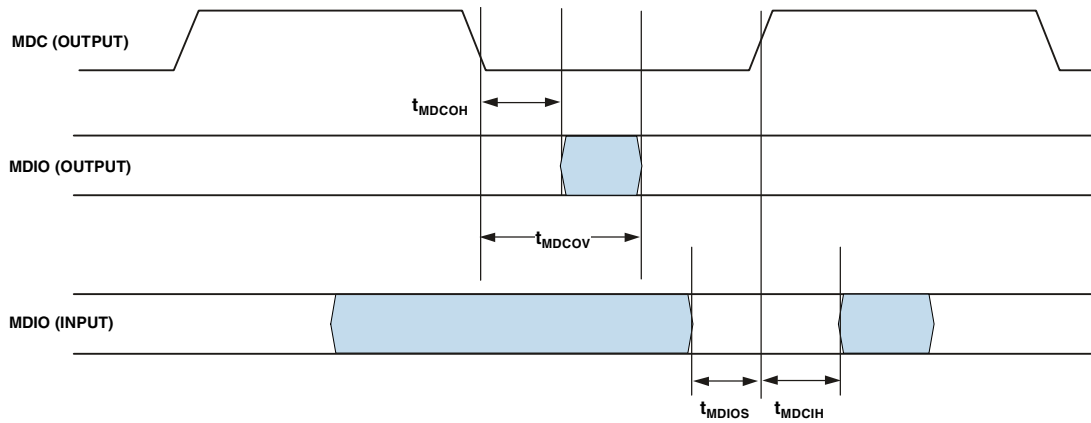


Figure 30. 10/100 Ethernet MAC Controller Timing: MII Station Management

OUTPUT DRIVE CURRENTS

Figure 31 through Figure 42 show typical current-voltage characteristics for the output drivers of the ADSP-BF512/514/516 processor. The curves represent the current drive capability of the output drivers as a function of output voltage. See Table 9 on Page 20 for information about which driver type corresponds to a particular pin/ball.

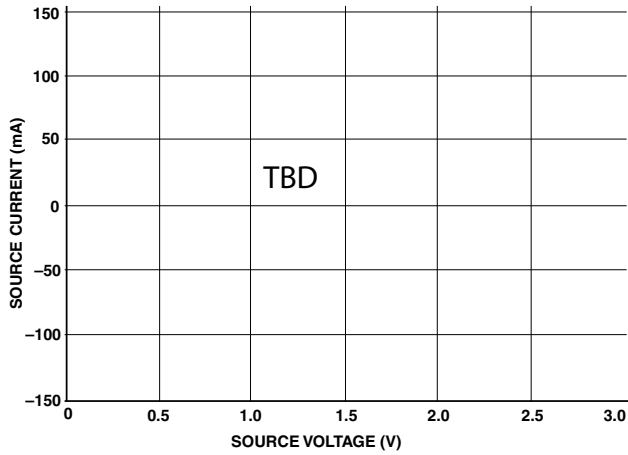


Figure 31. Drive Current A (Low V_{DDEXT})

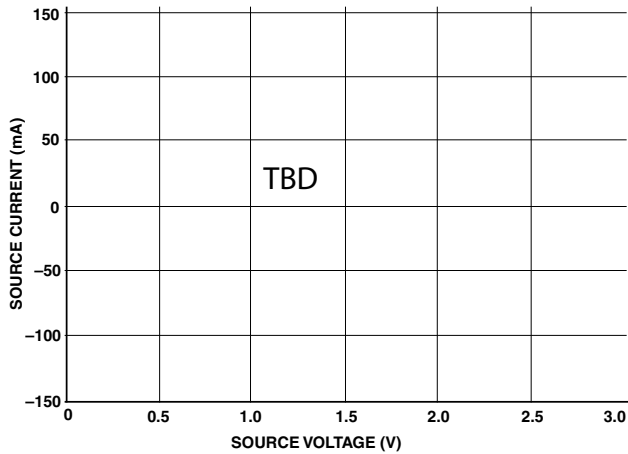


Figure 32. Drive Current A (High V_{DDEXT})

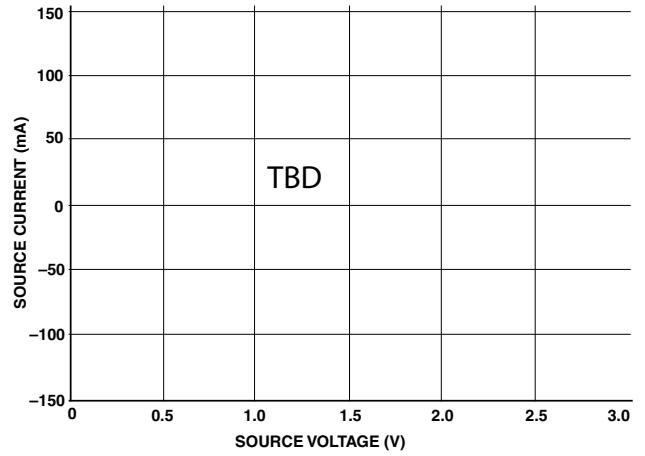


Figure 33. Drive Current B (Low V_{DDEXT})

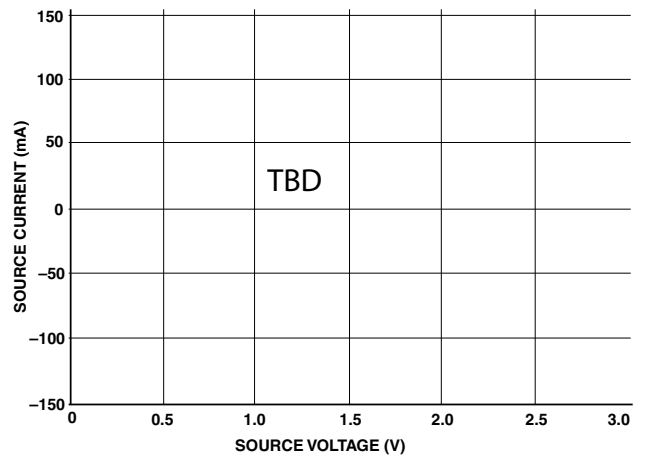


Figure 34. Drive Current B (High V_{DDEXT})

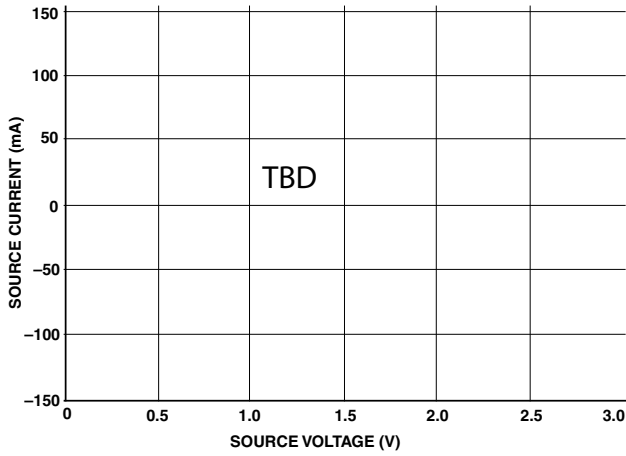


Figure 35. Drive Current C (Low V_{DDEXT})

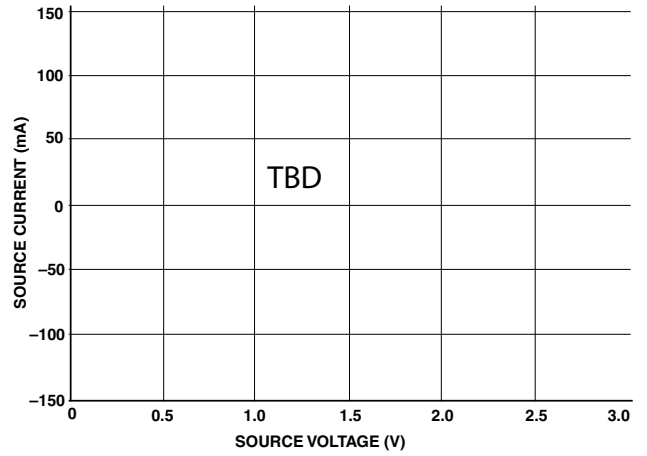


Figure 37. Drive Current D (Low V_{DDEXT})

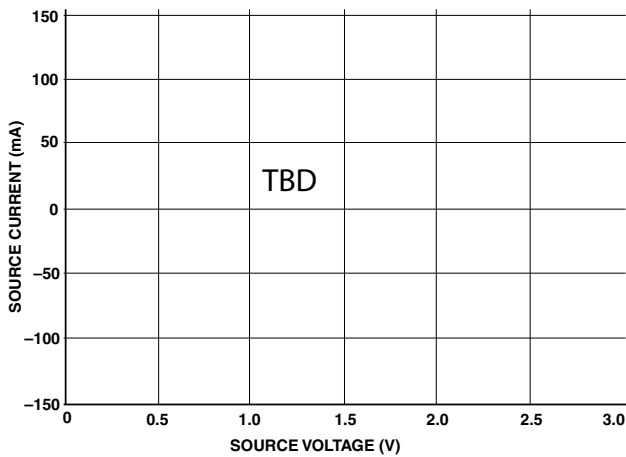


Figure 36. Drive Current C (High V_{DDEXT})

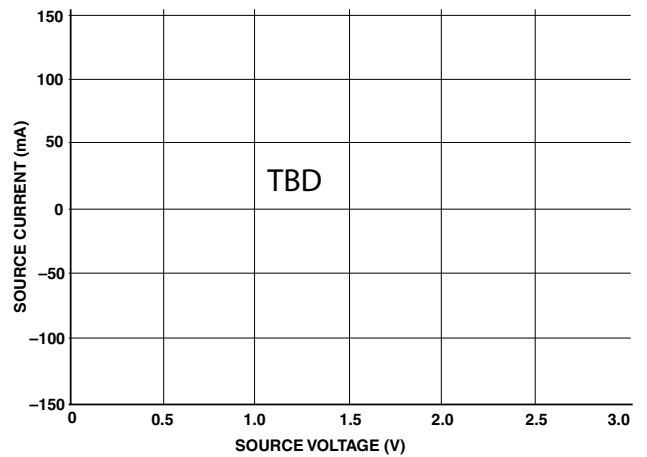


Figure 38. Drive Current D (High V_{DDEXT})

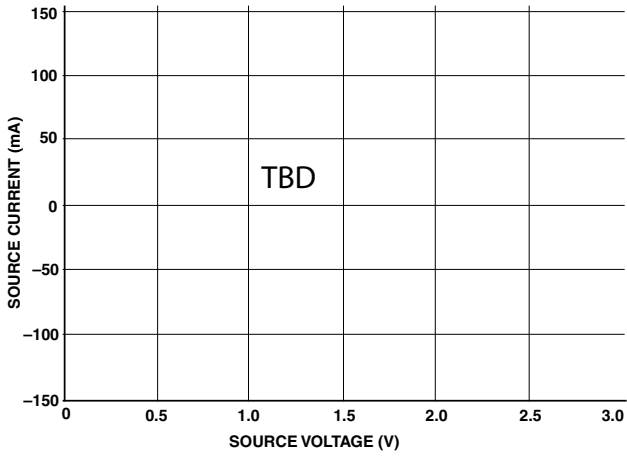


Figure 39. Drive Current E (Low V_{DDEXT})

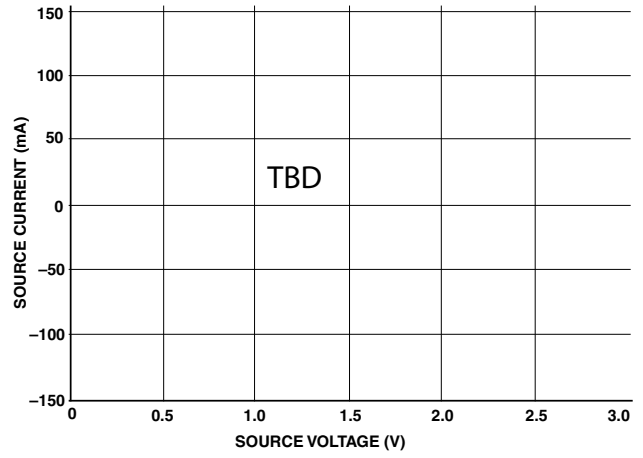


Figure 41. Drive Current F (Low V_{DDEXT})

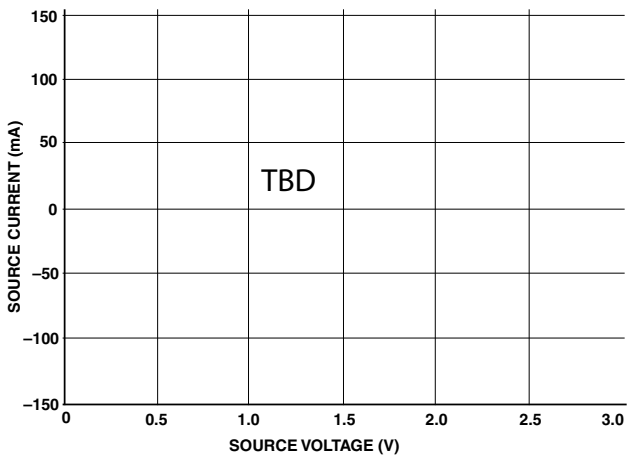


Figure 40. Drive Current E (High V_{DDEXT})

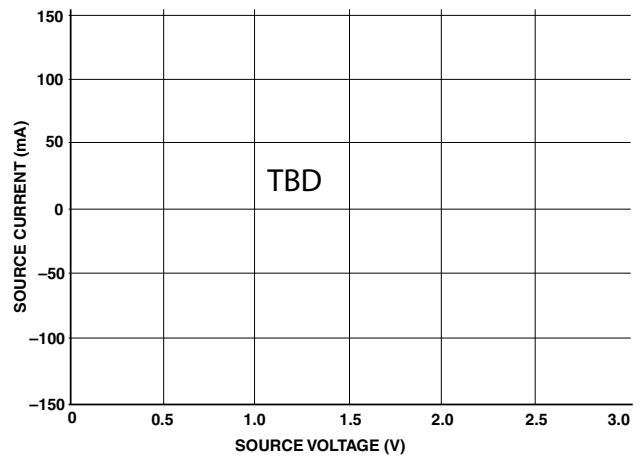


Figure 42. Drive Current F (High V_{DDEXT})

POWER DISSIPATION

Total power dissipation has two components: one due to internal circuitry (P_{INT}) and one due to the switching of external output drivers (P_{EXT}).

See the *ADSP-BF51x Blackfin Processor Hardware Reference Manual* for definitions of the various operating modes and for instructions on how to minimize system power.

Many operating conditions can affect power dissipation. System designers should refer to (*EE-tbd*) *Estimating Power for ADSP-BF512/514/516 Blackfin Processors* on the Analog Devices website (www.analog.com)—use site search on “EE-tbd.” That document provides detailed information for optimizing your design for lowest power.

TEST CONDITIONS

All timing parameters appearing in this data sheet were measured under the conditions described in this section. Figure 43 shows the measurement point for AC measurements (except output enable/disable). The measurement point V_{MEAS} is 1.5 V for V_{DDEXT} (nominal) = 2.5 V/3.3 V.

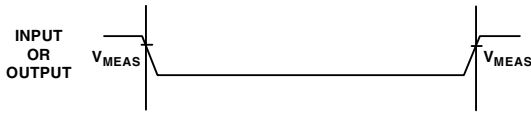


Figure 43. Voltage Reference Levels for AC Measurements (Except Output Enable/Disable)

Output Enable Time Measurement

Output signals are considered to be enabled when they have made a transition from a high impedance state to the point when they start driving.

The output enable time t_{ENA} is the interval from the point when a reference signal reaches a high or low voltage level to the point when the output starts driving as shown on the right side of Figure 44.

The time $t_{ENA_MEASURED}$ is the interval, from when the reference signal switches, to when the output voltage reaches V_{TRIP} (high) or V_{TRIP} (low). V_{TRIP} (high) is 2.0 V and V_{TRIP} (low) is 1.0 V for V_{DDEXT} (nominal) = 2.5 V/3.3 V. Time t_{TRIP} is the interval from when the output starts driving to when the output reaches the V_{TRIP} (high) or V_{TRIP} (low) trip voltage.

Time t_{ENA} is calculated as shown in the equation:

$$t_{ENA} = t_{ENA_MEASURED} - t_{TRIP}$$

If multiple signals (such as the data bus) are enabled, the measurement value is that of the first signal to start driving.

Output Disable Time Measurement

Output signals are considered to be disabled when they stop driving, go into a high impedance state, and start to decay from their output high or low voltage. The output disable time t_{DIS} is the difference between $t_{DIS_MEASURED}$ and t_{DECAY} as shown on the left side of Figure 44.

$$t_{DIS} = t_{DIS_MEASURED} - t_{DECAY}$$

The time for the voltage on the bus to decay by ΔV is dependent on the capacitive load C_L and the load current I_L . This decay time can be approximated by the equation:

$$t_{DECAY} = (C_L \Delta V) / I_L$$

The time t_{DECAY} is calculated with test loads C_L and I_L , and with ΔV equal to 0.5 V for V_{DDEXT} (nominal) = 2.5 V/3.3 V.

The time $t_{DIS_MEASURED}$ is the interval from when the reference signal switches, to when the output voltage decays ΔV from the measured output high or output low voltage.

Example System Hold Time Calculation

To determine the data output hold time in a particular system, first calculate t_{DECAY} using the equation given above. Choose ΔV to be the difference between the ADSP-BF512/514/516 processor's output voltage and the input threshold for the device requiring the hold time. C_L is the total bus capacitance (per data line), and I_L is the total leakage or three-state current (per data line). The hold time will be t_{DECAY} plus the various output disable times as specified in the Timing Specifications on Page 26 (for example t_{DSDAT} for an SDRAM write cycle as shown in SDRAM Interface Timing on Page 30).

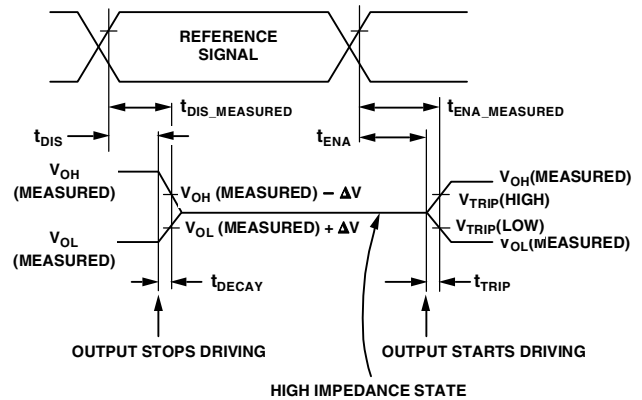


Figure 44. Output Enable/Disable

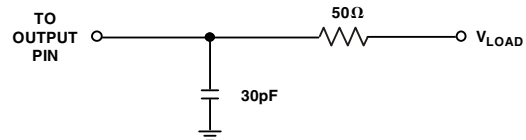


Figure 45. Equivalent Device Loading for AC Measurements (Includes All Fixtures)

Capacitive Loading

Output delays and holds are based on standard capacitive loads: 30 pF on all pins/balls (see Figure 45). V_{LOAD} is 1.5 V for V_{DDEXT} (nominal) = 2.5 V/3.3 V. Figure 46 on Page 53 through Figure 53 on Page 54 show how output rise time varies with capacitance. The delay and hold specifications given should be derated by a factor derived from these figures. The graphs in these figures may not be linear outside the ranges shown.

TBD

TBD

Figure 46. Typical Rise and Fall Times (10%–90%) versus Load Capacitance for Driver A at $EVDD_{MIN}$

Figure 49. Typical Rise and Fall Times (10%–90%) versus Load Capacitance for Driver B at $EVDD_{MAX}$

TBD

TBD

Figure 47. Typical Rise and Fall Times (10%–90%) versus Load Capacitance for Driver A at $EVDD_{MAX}$

Figure 50. Typical Rise and Fall Times (10%–90%) versus Load Capacitance for Driver C at $EVDD_{MIN}$

TBD

TBD

Figure 48. Typical Rise and Fall Times (10%–90%) versus Load Capacitance for Driver B at $EVDD_{MIN}$

Figure 51. Typical Rise and Fall Times (10%–90%) versus Load Capacitance for Driver C at $EVDD_{MAX}$

TBD

ENVIRONMENTAL CONDITIONS

To determine the junction temperature on the application printed circuit board use:

$$T_J = T_{CASE} + (\Psi_{JT} \times P_D)$$

where:

T_J = Junction temperature (°C)

T_{CASE} = Case temperature (°C) measured by customer at top center of package.

Ψ_{JT} = From Table 41

P_D = Power dissipation (see Power Dissipation on Page 51 for the method to calculate P_D)

Values of θ_{JA} are provided for package comparison and printed circuit board design considerations. θ_{JA} can be used for a first order approximation of T_J by the equation:

$$T_J = T_A + (\theta_{JA} \times P_D)$$

where:

T_A = Ambient temperature (°C)

Values of θ_{JC} are provided for package comparison and printed circuit board design considerations when an external heat sink is required.

Values of θ_{JB} are provided for package comparison and printed circuit board design considerations.

In Table 41, airflow measurements comply with JEDEC standards JESD51-2 and JESD51-6, and the junction-to-board measurement complies with JESD51-8. The junction-to-case measurement complies with MIL-STD-883 (Method 1012.1). All measurements use a 2S2P JEDEC test board.

Table 40. Thermal Characteristics (tbd-Ball CSP_BGA)

Parameter	Condition	Typical	Unit
θ_{JA}	0 linear m/s air flow	tbd	°C/W
θ_{JMA}	1 linear m/s air flow	tbd	°C/W
θ_{JMA}	2 linear m/s air flow	tbd	°C/W
θ_{JB}		tbd	°C/W
θ_{JC}		tbd	°C/W

Table 41. Thermal Characteristics (176-Lead LQFP)

Parameter	Condition	Typical	Unit
θ_{JA}	0 linear m/s air flow	tbd	°C/W
θ_{JMA}	1 linear m/s air flow	tbd	°C/W
θ_{JMA}	2 linear m/s air flow	tbd	°C/W
θ_{JB}		tbd	°C/W
θ_{JC}		tbd	°C/W

Figure 52. Typical Rise and Fall Times (10%–90%) versus Load Capacitance for Driver D at $EVDD_{MIN}$

TBD

Figure 53. Typical Rise and Fall Times (10%–90%) versus Load Capacitance for Driver D at $EVDD_{MAX}$

176-LEAD LQFP LEAD ASSIGNMENT

Table 42 lists the LQFP leads by signal mnemonic. Table 43 on Page 56 lists the LQFP by lead number.

Table 42. 176-Lead LQFP Lead Assignment (Alphabetically by Signal)

Signal	Lead No.	Signal	Lead No.	Signal	Lead No.	Signal	Lead No.	Signal	Lead No.	Signal	Lead No.	Signal	Lead No.

Table 42. 176-Lead LQFP Lead Assignment (Alphabetically by Signal) (Continued)

Signal	Lead No.	Signal	Lead No.	Signal	Lead No.	Signal	Lead No.	Signal	Lead No.	Signal	Lead No.	Signal	Lead No.

Table 43. 176-Lead LQFP Lead Assignment (Numerically by Lead Number)

Lead No.	Signal	Lead No.	Signal	Lead No.	Signal	Lead No.	Signal	Lead No.	Signal	Lead No.	Signal	Lead No.	Signal

Table 43. 176-Lead LQFP Lead Assignment (Numerically by Lead Number) (Continued)

Lead No.	Signal	Lead No.	Signal	Lead No.	Signal	Lead No.	Signal	Lead No.	Signal	Lead No.	Signal

Figure 55 shows the top view of the 176-Lead LQFP lead configuration. Figure 54 shows the bottom view of the 176-Lead LQFP lead configuration.

TBD

Figure 54. 176-Lead LQFP lead Configuration (Top View)

TBD

Figure 55. 176-Lead LQFP lead Configuration (Bottom View)

TBD-BALL CSP_BGA BALL ASSIGNMENT

Table 44 lists the CSP_BGA balls by signal mnemonic. Table 45 on Page 60 lists the CSP_BGA by ball number.

Table 44. tbd-Ball CSP_BGA Ball Assignment (Alphabetically by Signal)

Signal	Ball No.	Signal	Ball No.	Signal	Ball No.	Signal	Ball No.	Signal	Ball No.	Signal	Ball No.

Table 45. tbd-Ball CSP_BGA Ball Assignment (Numerically by Ball Number)

Ball No.	Signal	Ball No.	Signal	Ball No.	Signal	Ball No.	Signal	Ball No.	Signal

Figure 56 shows the top view of the CSP_BGA ball configuration. Figure 57 shows the bottom view of the CSP_BGA ball configuration.

TBD

Figure 56. *tbd-Ball CSP_BGA Ball Configuration (Top View)*

TBD

Figure 57. *tbd-Ball CSP_BGA Ball Configuration (Bottom View)*

OUTLINE DIMENSIONS

Dimensions in [Figure 58, 176-Lead LQFP](#) are shown in millimeters.

TBD

Figure 58. 176-Lead LQFP

SURFACE MOUNT DESIGN

The following table is provided as an aide to PCB design. For industry-standard design recommendations, refer to IPC-7351, *Generic Requirements for Surface Mount Design and Land Pattern Standard*.

TBD

Figure 59. tbd-Ball CSP_BGA

Table 46.

Package	Ball Attach Type	Solder Mask Opening	Ball Pad Size
tbd-Ball CSP_BGA	Solder Mask Defined	tbd mm diameter	tbd mm diameter

ORDERING GUIDE

Model	Temperature Range ¹	Package Description	Package Option	Instruction Rate (Max)	Operating Voltage (Nom)
tbd	-0°C to +70°C	176-Lead LQFP		400 MHz	tbd V internal, 1.8 V, 2.5 V, or 3.3 V I/O
tbd	-0°C to +70°C	tbd-Ball Chip Scale Package Ball Grid Array (CSP_BGA)	BC-tbd-1	400 MHz	tbd V internal, 1.8 V, 2.5 V, or 3.3 V I/O

¹ Referenced temperature is ambient temperature.

